HF2500

CC2500 Single Chip Low Cost Low Power RF Transceiver

Applications

- 2400-2483.5 MHz ISM/SRD band systems
- Consumer Electronics
- Wireless game controllers

Product Description

The **CC2500** is a low cost true single chip 2.4 GHz transceiver designed for very low power wireless applications. The circuit is intended for the ISM (Industrial, Scientific and Medical) and SRD (Short Range Device) frequency band at 2400-2483.5 MHz.

The RF transceiver is integrated with a highly configurable baseband modem. The modem supports various modulation formats and has a configurable data rate up to 500 kbps. The communication range can be increased by enabling a Forward Error Correction option, which is integrated in the modem.

CC2500 provides extensive hardware support for packet handling, data buffering, burst transmissions, clear channel assessment, link quality indication and wake-on-radio.

The main operating parameters and the 64byte transmit/receive FIFOs of **CC2500** can be

Key Features

- Small size (QLP 4x4 mm package, 20 pins)
- True single chip 2.4 GHz RF transceiver
- Frequency range: 2400-2483.5 MHz
- High sensitivity (-101 dBm at 10 kbps, 1% packet error rate)
- Programmable data rate up to 500 kbps
- Low current consumption (13.3 mA in RX, 250 kbps, input 30 dB above sensitivity limit)
- Programmable output power up to +1 dBm
- Excellent receiver selectivity and blocking performance
- Very few external components: Completely on-chip frequency synthesizer, no external filters or RF switch needed
- Programmable baseband modem
- Ideal for multi-channel operation
- Configurable packet handling hardware

- Wireless audio
- Wireless keyboard and mouse

controlled via an SPI interface. In a typical system, the **CC2500** will be used together with a microcontroller and a few additional passive components.

CC2500 is based on Chipcon's SmartRF[®]04 technology in 0.18 μ m CMOS.



- Suitable for frequency hopping systems due to a fast settling frequency synthesizer
- Optional Forward Error Correction with interleaving
- Separate 64-byte RX and TX data FIFOs
- Efficient SPI interface: All registers can be programmed with one "burst" transfer
- Digital RSSI output
- Suited for systems compliant with EN 300 328 and EN 300 440 class 2 (Europe), CFR47 Part 15 (US), and ARIB STD-T66 (Japan)
- Wake-on-radio functionality for automatic low-power RX polling
- Many powerful digital features allow a high-performance RF system to be made using an inexpensive microcontroller
- Integrated analog temperature sensor
- Lead-free "green" package



EE2500

Features (continued from front page)

- Flexible support for packet oriented systems: On chip support for sync word detection, address check, flexible packet length and automatic CRC handling.
- Programmable channel filter bandwidth
- 2-FSK, GFSK and MSK supported
- OOK supported
- Automatic Frequency Compensation can be used to align the frequency synthesizer to received centre frequency
- Optional automatic whitening and dewhitening of data
- Support for asynchronous transparent receive/transmit mode for backwards

compatibility with existing radio communication protocols

- Programmable Carrier Sense indicator
- Programmable Preamble Quality Indicator for detecting preambles and improved protection against sync word detection in random noise
- Support for automatic Clear Channel Assessment (CCA) before transmitting (for listen-before-talk systems)
- Support for per-package Link Quality Indication

Abbreviations

Abbreviations used in this data sheet are described below.

2-FSK	Binary Frequency Shift Keying	MSK	Minimum Shift Keying
ADC	Analog to Digital Converter	NA	Not Applicable
AFC	Automatic Frequency Offset Compensation	PA	Power Amplifier
AGC	Automatic Gain Control	PCB	Printed Circuit Board
AMR	Automatic Meter Reading	PD	Power Down
ASK	Amplitude Shift Keying	PER	Packet Error Rate
BER	Bit Error Rate	PLL	Phase Locked Loop
CCA	Clear Channel Assessment	POR	Power-on Reset
CRC	Cyclic Redundancy Check	PQI	Preamble Quality Indicator
CS	Carrier Sense	PQT	Preamble Quality Threshold
DC	Direct Current	RCOSC	RC Oscillator
EIRP	Equivalent Isotropic Radiated Power	RF	Radio Frequency
ESR	Equivalent Series Resistance	RSSI	Received Signal Strength Indicator
FEC	Forward Error Correction	RX	Receive, Receive Mode
FIFO	First-In-First-Out	SAW	Surface Aqustic Wave
FHSS	Frequency Hopping Spread Spectrum	SNR	Signal to Noise Ratio
FSK	Frequency Shift Keying	SPI	Serial Peripheral Interface
GFSK	Gaussian shaped Frequency Shift Keying	TBD	To Be Defined
IF	Intermediate Frequency	ТХ	Transmit, Transmit Mode
LBT	Listen Before Transmit	VCO	Voltage Controlled Oscillator
LNA	Low Noise Amplifier	WOR	Wake on Radio, Low power polling
LO	Local Oscillator	XOSC	Crystal Oscillator
LQI	Link Quality Indicator	XTAL	Crystal
MCU	Microcontroller Unit		





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1 Absolute Maximum Ratings

Under no circumstances must the absolute maximum ratings given in Table 1 be violated. Stress exceeding one or more of the limiting values may cause permanent damage to the device.

	Caution!	ESD	sensitive	device.
At A			e used when to prevent pe	

Parameter	Min	Max	Units	Condition
Supply voltage	-0.3	3.6	V	All supply pins must have the same voltage
Voltage on any digital pin	-0.3	VDD+0.3	V	
		max 3.6		
Voltage on the pins RF_P, RF_N and DCOUPL	-0.3	2.0	V	
Voltage ramp-up rate		120	kV/µs	
Input RF level		+10	dBm	
Storage temperature range	-50	150	°C	
Solder reflow temperature		260	°C	T = 10 s

Table 1: Absolute Maximum Ratings

2 Operating Conditions

The operating conditions for *CC2500* are listed Table 2 in below.

Parameter	Min	Max	Unit	Condition
Operating temperature	-40	85	°C	
Operating supply voltage	1.8	3.6	V	All supply pins must have the same voltage

Table 2: Operating Conditions

3 General Characteristics

Parameter	Min	Тур	Max	Unit	Condition/Note
Frequency range	2400		2483.5	MHz	
Data rate	1.2		500	kbps	Modulation formats supported: (Shaped) MSK (also known as differential offset QPSK) up to 500 kbps 2-FSK up to 500 kbps GFSK and OOK (up to 250 kbps)
					Optional Manchester encoding (halves the data rate).

Table 3: General Characteristics



CC2500

4 Electrical Specifications

4.1 Current Consumption

Tc = 25°C, VDD = 3.0 V if nothing else stated. All measurements were performed using the CC2500EM reference design.

Parameter	Min	Тур	Мах	Unit	Condition
Current consumption in power down modes		400		nA	Voltage regulator to digital part off, register values retained (SLEEP state)
		900		nA	Voltage regulator to digital part off, register values retained, low- power RC oscillator running (SLEEP state with WOR enabled)
		92		μA	Voltage regulator to digital part off, register values retained, XOSC running (SLEEP state with MCSM0.OSC_FORCE_ON set)
		157		μΑ	Voltage regulator to digital part on, all other modules in power down (XOFF state)
Current consumption		1.4		μΑ	Automatic RX polling once each second, using low-power RC oscillator, with 460 kHz filter bandwidth and 250 kbps data rate, PLL calibration every 4 th wakeup. Average current with signal in channel <i>below</i> carrier sense level.
		17		μA	Same as above, but with signal in channel <i>above</i> carrier sense level, 1.9 ms RX timeout, and no preamble/sync word found.
		0.9		μΑ	Automatic RX polling every 15 th second, using low-power RC oscillator, with 460 kHz filter bandwidth and 250 kbps data rate, PLL calibration every 4 th wakeup. Average current with signal in channel below carrier sense level.
		37		μA	Same as above, but with signal in channel <i>above</i> carrier sense level, 14 ms RX timeout, and no preamble/sync word found.
		1.5		mA	Only voltage regulator to digital part and crystal oscillator running (IDLE state)
		7.4		mA	Only the frequency synthesizer running (after going from IDLE until reaching RX or TX states, and frequency calibration states)
Current consumption, RX states		15.3		mA	Receive mode, 2.4 kbps, input at sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 1
		12.8		mA	Receive mode, 2.4 kbps, input 30 dB above sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 1
		15.4		mA	Receive mode, 10 kbps, input at sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 1
		12.9		mA	Receive mode, 10 kbps, input 30 dB above sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 1
		18.8		mA	Receive mode, 250 kbps, input at sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 0
		15.7		mA	Receive mode, 250 kbps, input 30 dB above sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 0
		16.6		mA	Receive mode, 250 kbps reduced current, input at sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 1
		13.3		mA	Receive mode, 250 kbps reduced current, input 30 dB above sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 1
		19.6		mA	Receive mode, 500 kbps, input at sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 0
		17.0		mA	Receive mode, 500 kbps, input 30 dB above sensitivity limit, MDMCFG2.DEM_DCFILT_OFF = 0
Current consumption,		11.1		mA	Transmit mode, –12 dBm output power
TX states		15.1	1	mA	Transmit mode, -6 dBm output power







Parameter	Min	Тур	Max	Unit	Condition
		21.2		mA	Transmit mode, 0 dBm output power
		21.5		mA	Transmit mode, 1.5 dBm output power

Table 4: Current Consumption

4.2 RF Receive Section

Tc = 25°C, VDD = 3.0 V if nothing else stated. All measurements were performed using the CC2500EM reference design.

Parameter	Min	Тур	Max	Unit	Condition/Note
Digital channel filter bandwidth	58		812	kHz	User programmable. The bandwidth limits are proportional to crystal frequency (given values assume a 26.0 MHz crystal).
2.4 kbps data rate, red (2-FSK, 1% packet erro					ILT_OFF = 1 (Hz digital channel filter bandwidth)
Receiver sensitivity		-104		dBm	The sensitivity can be improved to typically -106 dBm by setting MDMCFG2.DEM_DCFILT_OFF = 0. The typical current consumption is in this case 17.0 mA at sensitivity llimit.
Saturation		-13		dBm	
Adjacent channel rejection		23		dB	Desired channel 3 dB above the sensitivity limit. 250 kHz channel spacing
Alternate channel rejection		31		dB	Desired channel 3 dB above the sensitivity limit. 250 kHz channel spacing
					See Figure 17 for plot of selectivity versus frequency offset
10 kbps data rate, red (2-FSK, 1% packet error	uced co or rate, 2	urrent, MDM 20 bytes pac	CFG2.D	EM_DCF th, 232	· ILT_OFF = 1 KHz digital channel filter bandwidth)
Receiver sensitivity		-99		dBm	The sensitivity can be improved to typically -101 dBm by setting MDMCFG2.DEM_DCFILT_OFF = 0. The typical current consumption is in this case 17.3 mA at sensitivity llimit.
Saturation		-9		dBm	
Adjacent channel rejection		18		dB	Desired channel 3 dB above the sensitivity limit. 250 kHz channel spacing
Alternate channel rejection		25		dB	Desired channel 3 dB above the sensitivity limit. 250 kHz channel spacing
					See Figure 18 for plot of selectivity versus frequency offset
250 kbps data rate, MI (MSK, 1% packet error					Iz digital channel filter bandwidth)
Receiver sensitivity		-89		dBm	
Saturation		-13		dBm	
Adjacent channel rejection		21		dB	Desired channel 3 dB above the sensitivity limit. 750 kHz channel spacing
Alternate channel rejection		30		dB	Desired channel 3 dB above the sensitivity limit. 750 kHz channel spacing
					See Figure 19 for plot of selectivity versus frequency offset





Parameter	Min	Тур	Мах	Unit	Condition/Note				
	250 kbps data rate, reduced current, MDMCFG2.DEM_DCFILT_OFF = 1 (MSK, 1% packet error rate, 20 bytes packet length, 540 kHz digital channel filter bandwidth)								
Receiver sensitivity		-87		dBm					
Saturation		-13		dBm					
Adjacent channel rejection		21		dB	Desired channel 3 dB above the sensitivity limit. 750 kHz channel spacing				
Alternate channel rejection		30		dB	Desired channel 3 dB above the sensitivity limit. 750 kHz channel spacing				
					See Figure 20 for plot of selectivity versus frequency offset				
500 kbps data rate, MDMCFG2.DEM_DCFILT_OFF = 0 (MSK, 1% packet error rate, 20 bytes packet length, 812 kHz digital channel filter bandwidth)									
Receiver sensitivity		-82		dBm					
Saturation		-18		dBm					
Adjacent channel rejection		14		dB	Desired channel 3 dB above the sensitivity limit. 1 MHz channel spacing				
Alternate channel rejection		25		dB	Desired channel 3 dB above the sensitivity limit. 1 MHz channel spacing				
					See Figure 21 for plot of selectivity versus frequency offset				
General									
Selectivity at 10 MHz offset		47		dB	Desired channel at –80 dBm. Compliant with ETSI EN 300 440 class 2 receiver requirements.				
Selectivity at 20 MHz offset		52		dB	Desired channel at –80 dBm. Compliant with ETSI EN 300 440 class 2 receiver requirements.				
Selectivity at 50 MHz offset		54		dB	Desired channel at –80 dBm. Compliant with ETSI EN 300 440 class 2 receiver requirements.				
Spurious emissions									
25 MHz – 1 GHz			-57	dBm					
Above 1 GHz			-47	dBm					

Table 5: RF Receive Parameters





4.3 **RF Transmit Section**

 $Tc = 25^{\circ}C$, VDD = 3.0 V, 0 dBm if nothing else stated. All measurements were performed using the CC2500EM reference design.

Parameter	Min	Тур	Мах	Unit	Condition/Note
Differential load impedance		80 + j74		Ω	Differential impedance as seen from the RF-port (RF_P and RF_N) towards the antenna. Follow the CC2500EM reference design available from Chipcon's website.
Output power, highest setting		+1		dBm	Output power is programmable and is available across the entire frequency band
					Delivered to a 50 Ω single-ended load via Chipcon reference design RF matching network.
Output power, lowest setting		-30		dBm	Output power is programmable and is available across the entire frequency band
					Delivered to a 50 Ω single-ended load via Chipcon reference design RF matching network.
Spurious emissions					
25 MHz – 1 GHz			-36	dBm	
47-74, 87.5-118, 174-			-54	dBm	
230, 470-862 MHz					
1800-1900 MHz			-47	dBm	Restricted band in Europe
At 2·RF and 3·RF			-41	dBm	Restricted bands in USA
Otherwise above 1 GHz			-30	dBm	

Table 6: RF Transmit Parameters

4.4 Crystal Oscillator

Tc = 25° C, VDD = 3.0 V if nothing else stated.

Parameter	Min	Тур	Max	Unit	Condition/Note
Crystal frequency	26	26	27	MHz	
Tolerance		±40		ppm	This is the total tolerance including a) initial tolerance, b) crystal loading, c) aging and d) temperature dependence. The acceptable crystal tolerance depends on RF frequency and channel spacing / bandwidth.
ESR			100	Ω	
Start-up time		300		μs	Measured on Chipcon's CC2500EM reference design.

 Table 7: Crystal Oscillator Parameters





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4.5 Low Power RC Oscillator

Typical performance is for $Tc = 25^{\circ}C \otimes VDD = 3.0 V$ if nothing else is stated. The values in the table are simulated results and will be updated in later versions of the data sheet.

Parameter	Min	Тур	Max	Unit	Condition/Note
Calibrated frequency	34.6	34.7	36	kHz	Calibrated RC Oscillator frequency is XTAL frequency divided by 750
Frequency accuracy after calibration			+0.3 -10	%	
Temperature coefficient		+0.4		% / °C	Frequency drift when temperature changes after calibration
Supply voltage coefficient		+3		% / V	Frequency drift when supply voltage changes after calibration
Initial calibration time		2		ms	When the RC Oscillator is enabled, calibration is continuously done in the background as long as the crystal oscillator is running.
Wake-up period	58e-6		59650	Seconds	Programmable, dependent on XTAL frequency

4.6 Frequency Synthesizer Characteristics

Tc = 25°C, VDD = 3.0 V if nothing else stated. All measurements were performed using the CC2500EM reference design.

Parameter	Min	Тур	Max	Unit	Condition/Note
Programmed frequency resolution	397	F _{XOSC} / 2 ¹⁶	412	Hz	26-27 MHz crystal.
Synthesizer frequency tolerance		±40		ppm	Given by crystal used. Required accuracy (including temperature and aging) depends on frequency band and channel bandwidth / spacing.
RF carrier phase noise		-78		dBc/Hz	@ 50 kHz offset from carrier
RF carrier phase noise		-78		dBc/Hz	@ 100 kHz offset from carrier
RF carrier phase noise		-81		dBc/Hz	@ 200 kHz offset from carrier
RF carrier phase noise		-90		dBc/Hz	@ 500 kHz offset from carrier
RF carrier phase noise		-100		dBc/Hz	@ 1 MHz offset from carrier
RF carrier phase noise		-108		dBc/Hz	@ 2 MHz offset from carrier
RF carrier phase noise		-116		dBc/Hz	@ 5 MHz offset from carrier
RF carrier phase noise		-127		dBc/Hz	@ 10 MHz offset from carrier
PLL turn-on / hop time		90		μS	Time from leaving the IDLE state until arriving in the RX, FSTXON or TX state, when not performing calibration. Crystal oscillator running.
PLL RX/TX and TX/RX settling time		10		μS	Settling time for the 1xIF frequency step from RX to TX, and vice versa.
PLL calibration time		18739		XOSC cycles	Calibration can be initiated manually, or automatically before entering or after leaving RX/TX.
	0.69	0.72	0.72	ms	Min/typ/max time is for 27/26/26 MHz crystal frequency.

Table 9: Frequency Synthesizer Parameters





4.7 Analog Temperature Sensor

The characteristics of the analog temperature sensor are listed in Table 10 below. Note that it is necessary to write 0xBF to the PTEST register to use the analog temperature sensor in the IDLE state.

Parameter	Min	Тур	Max	Unit	Condition/Note
Output voltage at -40°C		0.660		V	
Output voltage at 0°C		0.755		V	
Output voltage at +40°C		0.859		V	
Output voltage at +80°C		0.958		V	
Output voltage at +120°C		1.056		V	
Temperature coefficient		2.54		mV/°C	Fitted from –20°C to +80°C
Error in calculated temperature, calibrated		0		°C	From –20°C to +80°C when using 2.54 mV / °C, after 1-point calibration at room temperature
Current consumption increase when enabled		0.3		mA	

4.8 DC Characteristics

The DC Characteristics of *CC2500* are listed in Table 11 below.

Tc = 25° C if nothing else stated.

Digital Inputs/Outputs	Min	Max	Unit	Condition
Logic "0" input voltage	0	0.7	V	
Logic "1" input voltage	VDD-0.7	VDD	V	
Logic "0" output voltage	0	0.5	V	For up to 4 mA output current
Logic "1" output voltage	VDD-0.3	VDD	V	For up to 4 mA output current
Logic "0" input current	NA	-1	μA	Input equals 0V
Logic "1" input current	NA	1	μA	Input equals VDD

Table 11: DC Characteristics

4.9 Power-On Reset

When the power supply complies with the requirements in Table 12 below, proper Power-On-Reset functionality is guaranteed. Otherwise, the chip should be assumed to have unknown state until transmitting an SRES strobe over the SPI interface. See Section 19.1 on page 35 for further details.

Parameter	Min	Тур	Мах	Unit	Unit Condition/Note	
Power ramp-up time			5	ms	From 0 V until reaching 1.8 V	
Power off time	1			ms	Minimum time between power-on and power-off.	

Table 12: Power-On Reset Requirements





5 Pin Configuration



Figure 1: Pinout top view

Note: The exposed die attach pad **must** be connected to a solid ground plane as this is the main ground connection for the chip.



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Pin #	Pin name	Pin type	Description
1	SCLK	Digital Input	Serial configuration interface, clock input
2	SO	Digital Output	Serial configuration interface, data output.
	(GDO1)		Optional general output pin when CSn is high
3	GDO2	Digital Output	Digital output pin for general use:
			Test signals
			FIFO status signals
			Clear Channel Indicator
			Clock output, down-divided from XOSC
			Serial output RX data
4	DVDD	Power (Digital)	1.8 - 3.6 V digital power supply for digital I/O's and for the digital core voltage regulator
5	DCOUPL	Power (Digital)	1.6 - 2.0 V digital power supply output for decoupling.
			NOTE: This pin is intended for use with the <i>CC2500</i> only. It can not be used to provide supply voltage to other devices.
6	GDO0	Digital I/O	Digital output pin for general use:
	(ATEST)		Test signals
			FIFO status signals
			Clear Channel Indicator
			Clock output, down-divided from XOSC
			Serial output RX data
			Serial input TX data
			Also used as analog test I/O for prototype/production testing
7	CSn	Digital Input	Serial configuration interface, chip select
8	XOSC_Q1	Analog I/O	Crystal oscillator pin 1, or external clock input
9	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
10	XOSC_Q2	Analog I/O	Crystal oscillator pin 2
11	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
12	RF_P	RF I/O	Positive RF input signal to LNA in receive mode
			Positive RF output signal from PA in transmit mode
13	RF_N	RF I/O	Negative RF input signal to LNA in receive mode
			Negative RF output signal from PA in transmit mode
14	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
15	AVDD	Power (Analog)	1.8 - 3.6 V analog power supply connection
16	GND	Ground (Analog)	Analog ground connection
17	RBIAS	Analog I/O	External bias resistor for reference current
18	DGUARD	Power (Digital)	Power supply connection for digital noise isolation
19	GND	Ground (Digital)	Ground connection for digital noise isolation
20	SI	Digital Input	Serial configuration interface, data input
1			

Table 13: Pinout overview





6 Circuit Description



A simplified block diagram of *CC2500* is shown in Figure 2.

CC2500 features a low-IF receiver. The received RF signal is amplified by the low-noise amplifier (LNA) and down-converted in quadrature (I and Q) to the intermediate frequency (IF). At IF, the I/Q signals are digitised by the ADCs. Automatic gain control (AGC), fine channel filtering, demodulation bit/packet synchronization is performed digitally.

The transmitter part of *CC2500* is based on direct synthesis of the RF frequency.

The frequency synthesizer includes a completely on-chip LC VCO and a 90 degrees

7 Application Circuit

Only a few external components are required for using the **CC2500**. The recommended application circuit is shown in Figure 3. The external components are described in Table 14, and typical values are given in Table 15. Note that the PCB antenna alternative indicated in Figure 3 is preliminary and subject to changes. Performance for the PCB antenna alternative will be included in future revisions of this data sheet. phase shifter for generating the I and Q LO signals to the down-conversion mixers in receive mode.

A crystal is to be connected to XOSC_Q1 and XOSC_Q2. The crystal oscillator generates the reference frequency for the synthesizer, as well as clocks for the ADC and the digital part.

A 4-wire SPI serial interface is used for configuration and data buffer access.

The digital baseband includes support for channel configuration, packet handling and data buffering.

Bias resistor

The bias resistor R171 is used to set an accurate bias current.

Balun and RF matching

C122, C132, L121 and L131 form a balun that converts the differential RF signal on *CC2500* to a single-ended RF signal (C121 and C131 are also needed for DC blocking). Together



with an appropriate LC network, the balun components also transform the impedance to match a 50 Ω antenna (or cable). Component values for the RF balun and LC network are easily found using the SmartRF[®] Studio software. Suggested values are listed in Table 15.

Crystal

The crystal oscillator uses an external crystal with two loading capacitors (C81 and C101). See Section 26 on page 44 for details.

Power supply decoupling

The power supply must be properly decoupled close to the supply pins. Note that decoupling capacitors are not shown in the application circuit. The placement and the size of the decoupling capacitors are very important to achieve the optimum performance. Chipcon provides a reference design that should be followed closely.

Component	Description
C51	Decoupling capacitor for on-chip voltage regulator to digital part
C81/C101	Crystal loading capacitors, see Section 26 on page 44 for details
C121/C131	RF balun DC blocking capacitors
C122/C132	RF balun/matching capacitors
C123/C124	RF LC filter/matching capacitors
L121/L131	RF balun/matching inductors (inexpensive multi-layer type)
L122	RF LC filter inductor (inexpensive multi-layer type)
R171	Resistor for internal bias current reference
XTAL	26-27 MHz crystal, see Section 26 on page 44 for details

Table 14: Overview of external components (excluding supply decoupling capacitors)



Figure 3: Typical application and evaluation circuit (excluding supply decoupling capacitors)

Component	Value
C51	100 nF ±10%, 0402 X5R
C81	27 pF ±5%, 0402 NP0
C101	27 pF ±5%, 0402 NP0
C121	100 pF ±5%, 0402 NP0
C122	1.0 pF ±0.25 pF, 0402 NP0
C123	1.8 pF ±0.25 pF, 0402 NP0
C124	1.5 pF ±0.25 pF, 0402 NP0
C131	100 pF ±5%, 0402 NP0
C132	1.0 pF ±0.25 pF, 0402 NP0
L121	1.2 nH ±0.3 nH, 0402 monolithic, Murata LQG-15 series
L122	1.2 nH ±0.3 nH, 0402 monolithic, Murata LQG-15 series
L131	1.2 nH ±0.3 nH, 0402 monolithic, Murata LQG-15 series
R171	56 kΩ ±1%, 0402
XTAL	26.0 MHz surface mount crystal

 Table 15: Bill Of Materials for the application circuit

In the CC2500EM reference design LQG-15 series inductors from Murata have been used. Measurements have been performed with

8 Configuration Overview

CC2500 can be configured to achieve optimum performance for many different applications. Configuration is done using the SPI interface. The following key parameters can be programmed:

- Power-down / power up mode
- Crystal oscillator power-up / power-down
- Receive / transmit mode
- RF channel selection
- Data rate
- Modulation format
- RX channel filter bandwidth
- RF output power
- Data buffering with separate 64-byte receive and transmit FIFOs

multi-layer inductors from other manufacturers (e.g. Würth) and the measurement results were the same as when using the Murata part.

||||//ก|||||

- Packet radio hardware support
- Forward Error Correction with interleaving
- Data Whitening
- Wake-On-Radio (WOR)

Details of each configuration register can be found in Section 31, starting on page 49.

Figure 4 shows a simplified state diagram that explains the main *CC2500* states, together with typical usage and current consumption. For detailed information on controlling the *CC2500* state machine, and a complete state diagram, see Section 19, starting on page 34.

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Figure 4: Simplified state diagram, with typical usage and current consumption at 250 kbps data rate and MDMCFG2.DEM_DCFILT_OFF = 1 (reduced current)

9 Configuration Software

CC2500 can be configured using the SmartRF[®] Studio software, available for download from http://www.chipcon.com. The SmartRF[®] Studio software is highly recommended for obtaining optimum register settings, and for evaluating performance and functionality. A screenshot of the SmartRF[®] Studio user interface for *CC2500* is shown in Figure 5.





Figure 5: SmartRF[®] Studio user interface

10 4-wire Serial Configuration and Data Interface

CC2500 is configured via a simple 4-wire SPIcompatible interface (SI, SO, SCLK and CSn) where **CC2500** is the slave. This interface is also used to read and write buffered data. All address and data transfer on the SPI interface is done most significant bit first.

All transactions on the SPI interface start with a header byte containing a read/write bit, a burst access bit and a 6-bit address.

During address and data transfer, the CSn pin (Chip Select, active low) must be kept low. If CSn goes high during the access, the transfer will be cancelled. The timing for the address and data transfer on the SPI interface is shown in Figure 6 with reference to Table 16.

When CSn goes low, the MCU must wait until **CC2500** so pin goes low before starting to transfer the header byte. This indicates that the voltage regulator has stabilized and the crystal is running. Unless the chip was in the SLEEP or XOFF states, the so pin will always go low immediately after taking CSn low.

Figure 7 gives a brief overview of different register access types possible.





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Figure 6: Configuration registers write and read operations (A6 is the "burst" bit)

Parameter	Description	Min	Мах	Units
F _{SCLK}	SCLK frequency	0	10	MHz
t _{sp,pd}	CSn low to positive edge on SCLK, in power-down mode	TBD	-	μs
t _{sp}	CSn low to positive edge on SCLK, in active mode	TBD	-	ns
t _{ch}	Clock high	50	-	ns
t _{cl}	Clock low	50	-	ns
t _{rise}	Clock rise time	-	TBD	ns
t _{fall}	Clock rise time	-	TBD	ns
t _{sd}	Setup data to positive edge on SCLK	TBD	-	ns
t _{hd}	Hold data after positive edge on SCLK	TBD	-	ns
t _{ns}	Negative edge on SCLK to CSn high.	TBD	-	ns

Table 16: SPI interface timing requirements

CSn:	
Command strobe(s):	ADDR ADDR ADDR ADDR ADDR ADDR ADDR ADDR
Read or write register(s):	$\langle \text{ADDR}_{eg} \rangle \langle \text{DATA} \rangle \langle \text{ADDR}_{eg} \rangle \langle \text{DATA} \rangle \langle \text{ADDR}_{eg} \rangle \langle \text{DATA} \rangle \dots$
Read or write consecutive registers (burst):	$\langle ADDR_{Bgn} \rangle \Delta TA \langle DATA \rangle \Delta TA_{h+1} \rangle \Delta TA_{h+2} \rangle \dots$
Read or write n+1 bytes from/to RF FIFO:	(ADDR _{FFO})(DATA _{byte 0})(DATA _{byte 1})(DATA _{byte 2}) (DATA _{byte n})(DATA _{byte n})
Combinations:	$ \label{eq:address} $$ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$

Figure 7: Register access types

10.1 Chip Status Byte

When the header byte, data byte or command strobe is sent on the SPI interface, the chip status byte is sent by the *CC2500* on the so pin. The status byte contains key status signals, useful for the MCU. The first bit, s7, is

the CHIP_RDYn signal; this signal must go low before the first positive edge of SCLK. The CHIP_RDYn signal indicates that the crystal is running and the regulated digital supply voltage is stable.





Bits 6, 5 and 4 comprise the STATE value. This value reflects the state of the chip. The XOSC and power to the digital core is on in the IDLE state, but all other modules are in power down. The frequency and channel configuration should only be updated when the chip is in this state. The RX state will be active when the chip is in receive mode. Likewise, TX is active when the chip is transmitting. The last four bits (3:0) in the status byte contains FIFO_BYTES_AVAILABLE. For read operations, the FIFO_BYTES_AVAILABLE field contains the number of bytes available for reading from the RX FIFO. For write operations, the FIFO_BYTES_AVAILABLE field contains the number of bytes free for writing into the TX FIFO. When FIFO_BYTES_AVAILABLE=15, 15 or more bytes are available/free.

Table 17 gives a status byte summary.

Bits	Name	Description		
7	CHIP_RDYn	Stays high until power and crystal have stabilized. Should always be low when using the SPI interface.		
6:4	STATE[2:0]	Indicates	the current main state ma	chine mode
		Value	State	Description
		000	IDLE	Idle state (Also reported for some transitional states instead of SETTLING or CALIBRATE)
		001	RX	Receive mode
		010	ТХ	Transmit mode
		011	FSTXON	Frequency synthesizer is on, ready to start transmitting
		100	CALIBRATE	Frequency synthesizer calibration is running
		101	SETTLING	PLL is settling
		110	RXFIFO_OVERFLOW	RX FIFO has overflowed. Read out any useful data, then flush the FIFO with SFRX
		111	TXFIFO_UNDERFLOW	TX FIFO has underflowed. Acknowledge with SFTX
3:0	FIFO_BYTES_AVAILABLE[3:0]	The number of bytes available in the RX FIFO or free bytes in the TX FIFO (depends on the read/write-bit). If FIFO_BYTES_AVAILABLE=15, there are 15 or more bytes in RX FIFO or 49 or less bytes in the TX FIFO.		

 Table 17: Status byte summary

10.2 Register Access

The configuration registers of the *CC2500* are located on SPI addresses from 0×00 to $0 \times 2F$. Table 35 on page 51 lists all configuration registers. The detailed description of each register is found in Section 31.1, starting on page 54. All configuration registers can be both written to and read. The read/write bit controls if the register should be written to or read. When writing to registers, the status byte is sent on the SO pin each time a header byte or data byte is transmitted on the SI pin. When reading from registers, the status byte is sent on the SO pin each time a header byte is transmitted on the SI pin.

Registers with consecutive addresses can be accessed in an efficient way by setting the burst bit in the address header. The address sets the start address in an internal address counter. This counter is incremented by one each new byte (every 8 clock pulses). The burst access is either a read or a write access and must be terminated by setting CSn high.

For register addresses in the range 0x30-0x3D, the "burst" bit is used to select between status registers and command strobes (see below). The status registers can only be read. Burst read is not available for status registers, so they must be read one at a time.





10.3 Command Strobes

Command Strobes may be viewed as single byte instructions to **CC2500**. By addressing a Command Strobe register, internal sequences will be started. These commands are used to disable the crystal oscillator, enable receive mode, enable wake-on-radio etc. The 14 command strobes are listed in Table 34 on page 50.

The command strobe registers are accessed in the same way as for a register write operation, but no data is transferred. That is, only the R/W bit (set to 0), burst access (set to 0) and the six address bits (in the range 0x30 through 0x3D) are written. A command strobe may be followed by any other SPI access without pulling CSn high. The command strobes are executed immediately, with the exception of the SPWD and the SXOFF strobes that are executed when CSn goes high.

When writing command strobes, the status byte is sent on the so pin.

10.4 FIFO Access

The 64-byte TX FIFO and the 64-byte RX FIFO are accessed through the 0x3F address. When the read/write bit is zero, the TX FIFO is accessed, and the RX FIFO is accessed when the read/write bit is one.

The TX FIFO is write-only, while the RX FIFO is read-only.

The burst bit is used to determine if FIFO access is single byte or a burst access. The single byte access method expects address with burst bit set to zero and one data byte. After the data byte a new address is expected; hence, CSn can remain low. The burst access method expects one address byte and then consecutive data bytes until terminating the access by setting CSn high.

The following header bytes access the FIFOs:

- 0x3F: Single byte access to TX FIFO
- 0x7F: Burst access to TX FIFO
- 0xBF: Single byte access to RX FIFO
- OxFF: Burst access to RX FIFO

When writing to the TX FIFO, the status byte (see Section 10.1) is output for each new data byte on so, as shown in Figure 6. This status byte can be used to detect TX FIFO underflow

while writing data to the TX FIFO. Note that the status byte contains the number of bytes free *before* writing the byte in progress to the TX FIFO. When the last byte that fits in the TX FIFO is transmitted to the SI pin, the status byte received concurrently on the SO pin will indicate that one byte is free in the TX FIFO.

The transmit FIFO may be flushed by issuing a SFTX command strobe. Similarly, a SFRX command strobe will flush the receive FIFO. A SFTX or SFRX command strobe can only be issued in the IDLE, TXFIFO_UNDERLOW or RXFIFO_OVERFLOW state. Both FIFOs are flushed when going to the SLEEP state.

10.5 PATABLE Access

The 0x3E address is used to access the PATABLE, which is used for selecting PA power control settings. The SPI expects up to eight data bytes after receiving the address. By programming the PATABLE, controlled PA power ramp-up and ramp-down can be achieved. See Section 0 on page 40 for output power programming details.

The PATABLE is an 8-byte table that defines the PA control settings to use for each of the eight PA power values (selected by the 3-bit value FRENDO.PA_POWER). The table is written and read from the lowest setting (0) to the highest (7), one byte at a time. An index counter is used to control the access to the table. This counter is incremented each time a byte is read or written to the table, and set to the lowest index when CSn is high. When the highest value is reached the counter restarts at zero.

The access to the PATABLE is either single byte or burst access depending on the burst bit. When using burst access the index counter will count up; when reaching 7 the counter will restart at 0. The read/write bit controls whether the access is a write access (R/W=0) or a read access (R/W=1).

If one byte is written to the PATABLE and this value is to be read out then CSn must be set high before the read access in order to set the index counter back to zero.

Note that the content of the PATABLE is lost when entering the SLEEP state, except for the first byte (index 0).





11 Microcontroller Interface and Pin Configuration

In a typical system, *CC2500* will interface to a microcontroller. This microcontroller must be able to:

- Program *CC2500* into different modes,
- Read and write buffered data
- Read back status information via the 4-wire SPI-bus configuration interface (SI, SO, SCLK and CSn).

11.1 Configuration Interface

The microcontroller uses four I/O pins for the SPI configuration interface (SI, SO, SCLK and CSn). The SPI is described in Section 10 on page 19.

11.2 General Control and Status Pins

The **CC2500** has two dedicated configurable pins and one shared pin that can output internal status information useful for control software. These pins can be used to generate interrupts on the MCU. See Section 28 on page 45 for more details on the signals that can be programmed. The dedicated pins are called GDO0 and GDO2. The shared pin is the so pin in the SPI interface. The default setting for GDO1/SO is 3-state output. By selecting any other of the programming options the GDO1/SO pin will become a generic pin. When CSn is low, the pin will always function as a normal SO pin.

In the synchronous and asynchronous serial modes, the GDO0 pin is used as a serial TX data input pin while in transmit mode.

The GDO0 pin can also be used for an on-chip analog temperature sensor. By measuring the voltage on the GDO0 pin with an external ADC, the temperature can be calculated. Specifications for the temperature sensor are found in Section 4.7 on page 12.

The temperature sensor output is only available when the frequency synthesizer is enabled (e.g. the MANCAL, FSTXON, RX and TX states). It is necessary to write 0xBF to the PTEST register to use the analog temperature sensor in the IDLE state. Before leaving the

IDLE state, the PTEST register should be restored to its default value (0x7F).

11.3 Optional Radio Control Feature

The **CC2500** has an optional way of controlling the radio, by reusing SI, SCLK and CSn from the SPI interface. This feature allows for a simple three-pin control of the major states of the radio: SLEEP, IDLE, RX and TX.

This optional functionality is enabled with the MCSMO.PIN CTRL EN configuration bit.

State changes are commanded as follows: When CSn is high the SI and SCLK is set to the desired state according to Table 18. When CSn goes low the state of SI and SCLK is latched and a command strobe is generated internally according to the control coding. It is only possible to change state with this functionality. That means that for instance RX will not be restarted if SI and SCLK are set to RX and CSn toggles. When CSn is low the SI and SCLK has normal SPI functionality.

All pin control command strobes are executed immediately, except the SPWD strobe, which is delayed until CSn goes high.

CSn	SCLK	SI	Function
1	х	х	Chip unaffected by SCLK/SI
\downarrow	0	0	Generates SPWD strobe
\downarrow	0	1	Generates STX strobe
\downarrow	1	0	Generates SIDLE strobe
\downarrow	1	1	Generates SRX strobe
0	SPI mode	SPI mode	SPI mode (wakes up into IDLE if in SLEEP/XOFF)





12 Data Rate Programming

The data rate used when transmitting, or the data rate expected in receive is programmed by the MDMCFG3.DRATE_M and the MDMCFG4.DRATE_E configuration registers. The data rate is given by the formula below. As the formula shows, the programmed data rate depends on the crystal frequency.

$$R_{DATA} = \frac{\left(256 + DRATE_M\right) \cdot 2^{DRATE_E}}{2^{28}} \cdot f_{XOSC}$$

The following approach can be used to find suitable values for a given data rate:

$$DRATE_E = \left\lfloor \log_2 \left(\frac{R_{DATA} \cdot 2^{20}}{f_{XOSC}} \right) \right\rfloor$$
$$DRATE_M = \frac{R_{DATA} \cdot 2^{28}}{f_{XOSC} \cdot 2^{DRATE_E}} - 256$$

If DRATE_M is rounded to the nearest integer and becomes 256, increment DRATE_E and use DRATE M=0.

13 Receiver Channel Filter Bandwidth

In order to meet different channel width requirements, the receiver channel filter is programmable. The MDMCFG4.CHANBW_E and MDMCFG4.CHANBW_M configuration registers control the receiver channel filter bandwidth, which scales with the crystal oscillator frequency. The following formula gives the relation between the register settings and the channel filter bandwidth:

$$BW_{channel} = \frac{f_{XOSC}}{8 \cdot (4 + CHANBW_M) \cdot 2^{CHANBW_E}}$$

The *CC2500* supports the following channel filter bandwidths:

Data rate start	Typical data rate	Data rate stop	Data rate step size
0.8 kbps	1.2/2.4 kbps	3.17 kbps	0.0062 kbps
3.17 kbps	4.8 kbps	6.35 kbps	0.0124 kbps
6.35 kbps	9.6 kbps	12.7 kbps	0.0248 kbps
12.7 kbps	19.6 kbps	25.4 kbps	0.0496 kbps
25.4 kbps	38.4 kbps	50.8 kbps	0.0992 kbps
50.8 kbps	76.8 kbps	101.6 kbps	0.1984 kbps
101.6 kbps	153.6 kbps	203.1 kbps	0.3967 kbps
203.1 kbps	250 kbps	406.3 kbps	0.7935 kbps
406.3 kbps	500 kbps	500 kbps	1.5869 kbps

The data rate can be set from 1.2 kbps to 500 kbps with the minimum step size of:

 Table 19: Data rate step size

MDMCFG4.	MDMCFG4.CHANBW_E			
CHANBW_M	00	01	10	11
00	812	406	203	102
01	650	325	162	81
10	541	270	135	68
11	464	232	116	58

Table 20: Channel filter bandwidths [kHz] (assuming a 26 MHz crystal)

Above 300 kHz bandwidth, however, the sensitivity and blocking performance may be somewhat degraded. For best performance, the channel filter bandwidth should be selected so that the signal bandwidth occupies at most 80% of the channel filter bandwidth. The channel centre tolerance due to crystal accuracy should also be subtracted from the signal bandwidth. The following example illustrates this:

With the channel filter bandwidth set to 600 kHz, the signal should stay within 80% of 600 kHz



kHz, which is 480 kHz. Assuming 2.44 GHz frequency and \pm 20 ppm frequency uncertainty for both the transmitting device and the receiving device, the total frequency uncertainty is \pm 40 ppm of 2.44 GHz, which is



CC2500 contains an advanced and highly configurable demodulator. Channel filtering and frequency offset compensation is performed digitally. To generate the RSSI level (see Section 17.3 for more information) the signal level in the channel is estimated. Data filtering is also included for enhanced performance.

14.1 Frequency Offset Compensation

When using FSK, GFSK or MSK modulation, the demodulator will compensate for the offset and transmitter between the receiver frequency, within certain limits, by estimating the centre of the received data. This value is available in the FREQEST status register. Writing the value from FREQEST into FSCTRL0.FREQOFF the frequency synthesizer is automatically adjusted according to the estimated frequency offset.

Note that frequency offset compensation is not supported for OOK modulation.

14.2 Bit Synchronization

The bit synchronization algorithm extracts the clock from the incoming symbols. The algorithm requires that the expected data rate is programmed as described in Section 12 on page 24. Re-synchronization is performed continuously to adjust for error in the incoming symbol rate.

15 Packet Handling Hardware Support

The *CC2500* has built-in hardware support for packet oriented radio protocols.

In transmit mode, the packet handler will add the following elements to the packet stored in the TX FIFO:

• A programmable number of preamble bytes. 4 preamble bytes is recommended.

 ± 98 kHz. If the whole transmitted signal bandwidth is to be received within 480 kHz, the transmitted signal bandwidth should be maximum 480 kHz–2.98 kHz, which is 284 kHz.

14.3 Byte Synchronization

Byte synchronization is achieved by a continuous sync word search. The sync word is a 16 or 32 bit configurable field that is automatically inserted at the start of the packet by the modulator in transmit mode. The demodulator uses this field to find the byte boundaries in the stream of bits. The sync word will also function as a system identifier, since only packets with the correct predefined sync word will be received. The sync word detector correlates against the user-configured 16-bit sync word. The correlation threshold can be set to 15/16 bits match or 16/16 bits match. The sync word can be further qualified using preamble quality the indicator mechanism described below and/or a carrier sense condition. The sync word is programmed with SYNC1 and SYNC0.

In order to make false detections of sync words less likely, a mechanism called preamble quality indication (PQI) can be used to qualify the sync word. A threshold value for the preamble quality must be exceeded in order for a detected sync word to be accepted. See Section 17.2 on page 30 for more details.

- A two byte Synchronization Word. Can be duplicated to give a 4-byte sync word. (Recommended).
- Optionally whiten the data with a PN9 sequence.
- Optionally Interleave and Forward Error Code the data.
- Optionally compute and add a CRC checksum over the data field.







In receive mode, the packet handling support will de-construct the data packet:

- Preamble detection.
- Sync word detection.
- Optional one byte address check.
- Optionally compute and check CRC.
- Optionally append two status bytes (see Table 21 and Table 22) with RSSI value, Link Quality Indication and CRC status.

Bit	Field name	Description
7:0	RSSI	RSSI value

Table 21: Received packet status byte 1(first byte appended after the data)

Bit	Field name	Description
7	CRC_OK	1: CRC for received data OK (or CRC disabled)
		0: CRC error in received data
6:0	LQI	The Link Quality Indicator estimates how easily a received signal can be demodulated

Table 22: Received packet status byte 2(second byte appended after the data)

Note that register fields that control the packet handling features should only be altered when **CC2500** is in the IDLE state.

15.1 Data Whitening

From a radio perspective, the ideal over the air data are random and DC free. This results in the smoothest power distribution over the occupied bandwidth. This also gives the regulation loops in the receiver uniform operation conditions (no data dependencies).

Real world data often contain long sequences of zeros and ones. Performance can then be improved by whitening the data before transmitting, and de-whitening in the receiver. With **CC2500**, this can be done automatically by setting PKTCTRL0.WHITE_DATA=1. All data, except the preamble and the sync word, are then XOR-ed with a 9-bit pseudo-random (PN9) sequence before being transmitted. At the receiver end, the data are XOR-ed with the same pseudo-random sequence. This way, the whitening is reversed, and the original data appear in the receiver. Setting PKTCTRL0.WHITE_DATA=1 is recommended for all uses, except when over-the-air compatibility with other systems is needed.

15.2 Packet Format

The format of the data packet can be configured and consists of the following items:

- Preamble
- Synchronization word
- Length byte or constant programmable packet length
- Optional address byte
- Payload
- Optional 2 byte CRC

The preamble pattern is an alternating sequence of ones and zeros (01010101...). The minimum length of the preamble is programmable. When enabling TX, the modulator will start transmitting the preamble. When the programmed number of preamble bytes has been transmitted, the modulator will send the sync word and then data from the TX FIFO if data is available. If the TX FIFO is empty, the modulator will continue to send preamble bytes until the first byte is written to the TX FIFO. The modulator will then send the sync word and then the data bytes. The number of preamble bytes is programmed with the MDMCFG1.NUM_PREAMBLE value.

The synchronization word is a two-byte value set in the SYNC1 and SYNC0 registers. The sync word provides byte synchronization of the incoming packet. A one-byte sync word can be emulated by setting the SYNC1 value to the preamble pattern. It is also possible to emulate a 32 bit sync word by using MDMCFG2.SYNC_MODE=3 or 7. The sync word will then be repeated twice.

CC2500 supports both fixed packet length protocols and variable packet length protocols. Variable or fixed packet length mode can be used for packet up to 255 bytes. For longer packets, infinite packet length mode must be used.

Fixed packet length mode is selected by setting PKTCTRL0.LENGTH_CONFIG=0. The desired packet length is set by the PKTLEN register. The packet length is defined as the payload data, excluding the length byte and the optional automatic CRC. In variable length mode, PKTCTRL0.LENGTH_CONFIG=1, the packet length is configured by the first byte after the sync word. The PKTLEN register is





used to set the maximum packet length allowed in RX. Any packet received with a length byte with a value greater than PKTLEN will be discarded.

With PKTCTRLO.LENGTH_CONFIG=2, the packet length is set to infinite and transmission and reception will continue until turned off manually. The infinite mode can be turned off while a packet is being transmitted or received. As described in the next section, this can be used to support packet formats with different length configuration than natively supported by **CC2500**.

15.2.1 Arbitrary Length Field Configuration

The fixed length field can be reprogrammed during receive and transmit. This opens the possibility to have a different length field configuration than supported for variable length packets. At the start of reception, the packet length is set to a large value. The MCU reads out enough bytes to interpret the length field in the packet. Then the PKTLEN value is set according to this value. The end of packet will occur when the byte counter in the packet handler is equal to the PKTLEN register. Thus, the MCU must be able to program the correct length, before the internal counter reaches the packet length. By utilizing the infinite packet length option, arbitrary packet length is available. At the start of the packet, the infinite mode must be active. When less than 256 bytes remains of the packet, the MCU sets the PKTLEN register to mod(length, 256), disables infinite packet length and activates fixed length packets. When the internal byte counter reaches the PKTLEN value, the transmission or reception ends. Automatic CRC appending/checking can be used (by setting PKTCTRL0.CRC EN to 1).

When for example a 454-byte packet is to be transmitted, the MCU does the following:

- Set PKTCTRL0.LENGTH CONFIG=2 (10).
- Pre-program the PKTLEN register to mod(454,256)=198.
- Transmit at least 198 bytes, for example by filling the 64-byte TX FIFO four times (256 bytes transmitted).
- Set PKTCTRL0.LENGTH CONFIG=0 (00).
- The transmission ends when the packet counter reaches 198. A total of 256+198=454 bytes are transmitted.





15.3 Packet Filtering in Receive Mode

CC2500 supports three different packet-filtering criteria: address filtering, maximum length filtering and CRC filtering.

15.3.1 Adress Filtering

Setting PKTCTRL1.ADR_CHK to any other value than zero enables the packet address filter. The packet handler engine will compare the destination address byte in the packet with the programmed node address in the ADDR register and the 0x00 broadcast address when PKTCTRL1.ADR_CHK=10 or both 0x00 and

0xFF broadcast addresses when PKTCTRL1.ADR_CHK=11. If the received address matches a valid address, the packet is received and written into the RX FIFO. If the address match fails, the packet is discarded and receive mode restarted (regardless of the MCSM1.RXOFF_MODE setting).

15.3.2 Maximum Length Filtering

In the variable packet length mode the PKTLEN.PACKET_LENGTH register value is used to set the maximum allowed packet length. If the received length byte has a larger value than this, the packet is discarded and

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receive mode restarted (regardless of the MCSM1.RXOFF MODE setting).

15.3.3 CRC Filtering

The filtering of a packet when CRC check fails is enabled with PKTCTRL1.CRC_AUTOFLUSH. The CRC auto flush function will flush the *entire* RX FIFO if the CRC check fails. After auto flushing the RX FIFO, the next state depends on the MCSM1.RXOFF MODE setting.

When using the auto flush function, the maximum packet length is 63 bytes in variable packet length mode and 64 bytes in fixed packet length mode. Note that the maximum allowed packet length is reduced by two bytes when PKTCTRL1.APPEND STATUS is enabled, to make room in the RX FIFO for the two status bytes appended at the end of the packet. Since the entire RX FIFO is flushed when the CRC check fails, the previously received packet must be read out of the FIFO before receiving the current packet. The MCU must not read from the current packet until the CRC has been checked as OK.

15.4 CRC Check

It is possible to read back the CRC status in 2 different ways:

1) Set PKTCTRL1.APPEND_STATUS=1 and read the CRC_OK flag in the MSB of the second byte appended to the RX FIFO after the packet data. This requires double buffering of the packet, i.e. the entire packet content of the RX FIFO must be completely read out before it is possible to check whether the CRC indication is OK or not.

2) To avoid reading the whole RX FIFO, another solution is to use the PKTCTRL1.CRC AUTOFLUSH feature. If this feature is enabled, the entire RX FIFO will be flushed if the CRC check fails. lf GDOx CFG=0x06 the GDOx pin will be asserted when a sync word is found. The GDOx pin will be de-asserted at the end of the packet. When the latter occurs the MCU should read the number of bytes in the RX FIFO from the RXBYTES.NUM RXBYTES status register. If RXBYTES.NUM RXBYTES=0 the CRC check failed and the FIFO was flushed. If RXBYTES.NUM RXBYTES>0 the CRC check was OK and data can be read out of the FIFO.

15.5 Packet Handling in Transmit Mode

The payload that is to be transmitted must be written into the TX FIFO. The first byte written must be the length byte when variable packet length is enabled. The length byte has a value equal to the payload of the packet (including the optional address byte). If fixed packet length is enabled, then the first byte written to the TX FIFO is interpreted as the destination address, if this feature is enabled in the device that receives the packet.

The modulator will first send the programmed number of preamble bytes. If data is available in the TX FIFO, the modulator will send the two-byte (optionally 4-byte) sync word and then the payload in the TX FIFO. If CRC is enabled, the checksum is calculated over all the data pulled from the TX FIFO and the result is sent as two extra bytes at the end of the payload data.

If whitening is enabled, the length byte, payload data and the two CRC bytes will be whitened. This is done before the optional FEC/Interleaver stage. Whitening is enabled by setting PKTCTRL0.WHITE DATA=1.

If FEC/Interleaving is enabled, the length byte, payload data and the two CRC bytes will be scrambled by the interleaver, and FEC encoded before being modulated.

15.6 Packet Handling in Receive Mode

In receive mode, the demodulator and packet handler will search for a valid preamble and the sync word. When found, the demodulator has obtained both bit and byte synchronism and will receive the first payload byte.

If FEC/Interleaving is enabled, the FEC decoder will start to decode the first payload byte. The interleaver will de-scramble the bits before any other processing is done to the data.

If whitening is enabled, the data will be dewhitened at this stage.

When variable packet length is enabled, the first byte is the length byte. The packet handler stores this value as the packet length and receives the number of bytes indicated by the length byte. If fixed packet length is used, the packet handler will accept the programmed number of bytes.

Next, the packet handler optionally checks the address and only continues the reception if the address matches. If automatic CRC check is



enabled, the packet handler computes CRC and matches it with the appended CRC checksum.

16 Modulation Formats

CC2500 supports amplitude, frequency and phase shift modulation formats. The desired modulation format is set in the MDMCFG2.MOD FORMAT register.

Optionally, the data stream can be Manchester coded by the modulator and decoded by the demodulator. This option is enabled by setting MDMCFG2.MANCHESTER_EN=1. Manchester encoding is not supported at the same time as using the FEC/Interleaver option. Manchester coding can be used with the 2-ary modulation formats (2-FSK, GFSK, OOK and MSK).

16.1 Frequency Shift Keying

2-FSK can optionally be shaped by a Gaussian filter with BT=1, producing a GFSK modulated signal.

The frequency deviation is programmed with the DEVIATION_M and DEVIATION_E values in the DEVIATN register. The value has an exponent/mantissa form, and the resultant deviation is given by:

$$f_{dev} = \frac{f_{xosc}}{2^{17}} \cdot (8 + DEVIATION _M) \cdot 2^{DEVIATION_E}$$

The symbol encoding is shown in Table 23.

Format	Symbol	Coding
2-FSK/GFSK	ʻ0'	- Deviation
	'1'	+ Deviation

Table 23: Symbol encoding for FSK modulation

At the end of the payload, the packet handler will optionally write two extra packet status bytes that contain CRC status, link quality indication and RSSI value.

16.2 Minimum Shift Keying

When using MSK¹, the complete transmission (preamble, sync word and payload) will be MSK modulated.

Phase shifts are performed with a constant transition time. This means that the rate of change for the 180-degree transition is twice that of the 90-degree transition.

The fraction of a symbol period used to change the phase can be modified with the DEVIATN.DEVIATION_M setting. This is equivalent to changing the shaping of the symbol. Setting DEVIATN.DEVIATION_M=7 will generate a standard shaped MSK signal.

The MSK modulation format implemented in **CC2500** inverts the sync word and data compared to e.g. signal generators.

16.3 Amplitude Modulation

The supported amplitude modulation On-Off Keying (OOK) simply turns on or off the PA to modulate 1 and 0 respectively.

¹ Identical to offset QPSK with half-sine shaping (data coding may differ)



17 Received Signal Qualifiers and Link Quality Information

CC2500 has several qualifiers that can be used to increase the likelihood that a valid sync word is detected.

17.1 Sync Word Qualifier

If sync word detection in RX is enabled in register MDMCFG2 the **CC2500** will not start filling the RX FIFO and perform the packet filtering described in Section 15.3 before a valid sync word has been detected. The sync word qualifier mode is set by MDMCFG2.SYNC_MODE and is summarized in Table 24. Carrier sense in Table 24 is described in Section 17.4.

MDMCFG2.	Sync word qualifier mode
SYNC_MODE	
000	No preamble/sync
001	15/16 sync word bits detected
010	16/16 sync word bits detected
011	30/32 sync word bits detected
100	No preamble/sync, carrier sense above threshold
101	15/16 + carrier sense above threshold
110	16/16 + carrier sense above threshold
111	30/32 + carrier sense above threshold

 Table 24: Sync word qualifier mode

17.2 Preamble Quality Threshold (PQT)

The Preamble Quality Threshold (PQT) syncword qualifier adds the requirement that the received sync word must be preceded with a preamble with a quality above a programmed threshold.

Another use of the preamble quality threshold is as a qualifier for the optional RX termination timer. See Section 19.7 on page 37 for details.

The preamble quality estimator increases an internal counter by one each time a bit is received that is different from the previous bit, and decreases the counter by 4 each time a bit is received that is the same as the last bit. The counter saturates at 0 and 31. The threshold is configured with the register field

PKTCTRL1.PQT. A threshold of $4 \cdot PQT$ for this counter is used to gate sync word detection. By setting the value to zero, the preamble quality qualifier of the sync word is disabled.

A "Preamble Quality Reached" flag can also be observed on one of the GDO pins and in the status register bit PKTSTATUS.PQT_REACHED. This flag asserts when the received signal exceeds the PQT.

17.3 RSSI

The RSSI value is an estimate of the signal level in the current channel. This value is based on the current gain setting in the RX chain and the measured signal level in the channel.

In RX mode, the RSSI value can be read continuously from the RSSI status register, until the demodulator detects a sync word (when sync word detection is enabled). At that point, the RSSI readout value is frozen until the next time the chip enters the RX state. The RSSI value is in dB with ½dB resolution.

If PKTCTRL1.APPEND_STATUS is enabled, a snapshot of the RSSI during the first 8 bytes of the packet is automatically added to the end of each received packet.

The RSSI value read from the RSSI status register is a 2's complement number. The following procedure can be used to convert the RSSI reading to an absolute power level (RSSI_dBm).

- 1) Read the RSSI status register
- 2) Convert the reading from a hexadecimal number to a decimal number (RSSI_dec)
- 3) If RSSI_dec ≥ 128 then RSSI_dBm = (RSSI_dec 256)/2 RSSI_offset
- 4) Else if RSSI_dec < 128 then RSSI_dBm = (RSSI_dec)/2 – RSSI_offset

Table 25 gives typical values for the RSSI_offset.

Figure 9 shows typical plots of RSSI reading as a function of input power level for different data rates.



Data rate	RSSI_offset (decimal)
2.4 kbps	71
10 kbps	69
250 kbps	72
500 kbps	72

Table 25: Typical RSSI_offset values



Figure 9: Typical RSSI value vs. input power level for some typical data rates

17.4 Carrier Sense (CS)

The Carrier Sense flag is used as a sync word qualifier and for CCA. The CS flag can be set based on two conditions, which can be individually adjusted:

- CS is asserted when the RSSI is above a programmable absolute threshold, and deasserted when RSSI is below the same threshold (with hysteresis).
- CS is asserted when the RSSI has increased with a programmable number of dB from one RSSI sample to the next, and de-asserted when RSSI has decreased with the same number of dB. This setting is not dependent on the absolute signal level and is thus useful to detect signals in environments with a time varying noise floor.

Carrier Sense (CS) can be used as a sync word qualifier that requires the signal level to be higher than the threshold for a sync word search to be performed. The signal can also be observed on one of the GDO pins and in the status register bit PKTSTATUS.CS.

Other uses of Carrier Sense include the TX-If-CCA function (see Section 17.5 on page 32) and the optional fast RX termination (see Section 19.7 on page 37).

CS can be used to avoid interference from e.g. WLAN.

17.4.1 CS Absolute Threshold

The absolute threshold related to the RSSI value is given by:

 $THR_{RSSI} = MAGN _ TARGET + CARRIER _ SENSE _ ABS _ THR - GAIN_{MAX}$

The maximum possible gain can be reduced using the AGCCTRL2.MAX_LNA_GAIN and AGCCTRL2.MAX_DVGA_GAIN register fields. CARRIER_SENSE_ABS_THR is programmable in 1 dB steps from -7 dB to + 7dB. Table 26 and Table 27 show the RSSI readout values



at the CS threshold at 2.4 kbps and 250 kbps data rate respectively. The default CARRIER_SENSE_ABS_THR = 0 (0 dB) and MAGN_TARGET = 3 (33 dB) have been used.

		MAX_DVGA_GAIN[1:0]				
		00	01	10	11	
MAX_LNA_GAIN[2:0]	000	-99	-93	-87	-81.5	
	001	-97	-90.5	-85	-78.5	
	010	-93.5	-87	-82	-76	
	011	-91.5	-86	-80	-74	
	100	-90.5	-84	-78	-72.5	
	101	-88	-82.5	-76	-70	
	110	-84.5	-78.5	-73	-67	
	111	-82.5	-76	-70	-64	

Table 26: Typical RSSI value in dBm at CS threshold with default MAGN_TARGET at 2.4 kbps

		MAX_DVGA_GAIN[1:0]				
		00	01	10	11	
MAX_LNA_GAIN[2:0]	000	-96	-90	-84	-78.5	
	001	-94.5	-89	-83	-77.5	
	010	-92.5	-87	-81	-75	
	011	-91	-85	-78.5	-73	
	100	-87.5	-82	-76	-70	
	101	-85	-79.5	-73.5	-67.5	
	110	-83	-76.5	-70.5	-65	
	111	-78	-72	-66	-60	

Table 27: Typical RSSI value in dBm at CS threshold with default MAGN_TARGET at 250 kbps

If the threshold is to be set high, e.g. only signals with good strength are wanted, the threshold should be adjusted upwards by first reducing the MAX_LNA_GAIN value and then the MAX_DVGA_GAIN value. This will reduce power consumption in the receiver front end, since the highest gain settings are avoided.

The MAGN_TARGET setting is a compromise between blocker tolerance/selectivity and sensitivity. The value sets the desired signal level in the channel into the demodulator. Increasing this value reduces the headroom for blockers, and therefore close-in selectivity.

17.4.2 CS relative threshold

The relative threshold detects sudden changes in the measured signal level. This setting is not dependent on the absolute signal level and is thus useful to detect signals in environments with a time varying noise floor. The register field AGCCTRL1.CARRIER_SENSE_REL_THR is used to enable/disable relative CS, and to select threshold of 6 dB, 10 dB or 14 dB RSSI change

17.5 Clear Channel Assessment (CCA)

The Clear Channel Assessment is used to indicate if the current channel is free or busy. The current CCA state is viewable on any of the GDO pins.

MCSM1.CCA_MODE selects the mode to use when determining CCA.

When the STX or SFSTXON command strobe is given while **CC2500** is in the RX state, the TX state is only entered if the clear channel requirements are fulfilled. The chip will otherwise remain in RX. This feature is called TX if CCA.

Four CCA requirements can be programmed:

- Always (CCA disabled, always goes to TX)
- If RSSI is below threshold
- Unless currently receiving a packet
- Both the above (RSSI below threshold and not currently receiving a packet)

17.6 Link Quality Indicator (LQI)

The Link Quality Indicator is a metric of the current quality of the received signal. If PKTCTRL1.APPEND_STATUS is enabled, the value is automatically appended to the end of each received packet. The value can also be read from the LQI status register. The LQI is calculated over the 64 symbols following the sync word (first 8 packet bytes for 2-ary modulation). LQI is best used as a relative measurement of the link quality, since the value is dependent on the modulation format.



18 Forward Error Correction with Interleaving

18.1 Forward Error Correction (FEC)

CC2500 has built in support for Forward Error Correction (FEC). To enable this option, set MDMCFG1.FEC_EN to 1. FEC is employed on the data field and CRC word in order to reduce the gross bit error rate when operating near the sensitivity limit. Redundancy is added to the transmitted data in such a way that the receiver can restore the original data in the presence of some bit errors.

The use of FEC allows correct reception at a lower SNR, thus extending communication range. Alternatively, for a given SNR, using FEC decreases the bit error rate (BER). As the packet error rate (PER) is related to BER by:

$$PER = 1 - (1 - BER)^{packet_leng}$$

a lower BER can be used to allow longer packets, or a higher percentage of packets of a given length, to be transmitted successfully. Finally, in realistic ISM radio environments, transient and time-varying phenomena will produce occasional errors even in otherwise good reception conditions. FEC will mask such errors and, combined with interleaving of the coded data, even correct relatively long periods of faulty reception (burst errors).

The FEC scheme adopted for **CC2500** is convolutional coding, in which n bits are generated based on k input bits and the mmost recent input bits, forming a code stream able to withstand a certain number of bit errors between each coding state (the *m*-bit window).

The convolutional coder is a rate 1/2 code with a constraint length of m=4. The coder codes one input bit and produces two output bits; hence, the effective data rate is halved.

18.2 Interleaving

Data received through radio channels will often experience burst errors due to interference and time-varying signal strengths. In order to increase the robustness to errors spanning multiple bits, interleaving is used when FEC is enabled. After de-interleaving, a continuous span of errors in the received stream will become single errors spread apart.

CC2500 employs matrix interleaving, which is illustrated in Figure 10. The on-chip interleaving and de-interleaving buffers are 4 x 4 matrices. In the transmitter, the data bits are written into the rows of the matrix, whereas the bit sequence to be transmitted is read from the columns of the matrix and fed to the rate ½ convolutional coder. Conversely, in the receiver, the received symbols are written into the columns of the matrix, whereas the data passed onto the convolutional decoder is read from the rows of the matrix.

When FEC and interleaving is used, the amount of data transmitted over the air must be a multiple of the size of the interleaver buffer (two bytes). In addition, at least one extra byte is required for trellis termination. The packet control hardware therefore automatically inserts one or two extra bytes at the end of the packet, so that the total length of the data to be interleaved is an even number. Note that these extra bytes are invisible to the user, as they are removed before the received packet enters the RX FIFO.

Due to the implementation of the FEC and interleaver, the data to be interleaved must be at least two bytes. One byte long fixed length packets without CRC is therefore not supported when FEC/interleaving is enabled.



Figure 10: General principle of matrix interleaving





19 Radio Control



Figure 11: Complete radio control state diagram

CC2500 has a built-in state machine that is used to switch between different operation states (modes). The change of state is done either by using command strobes or by internal events such as TX FIFO underflow.

A simplified state diagram, together with typical usage and current consumption, is

shown in Figure 4 on page 13. The complete radio control state diagram is shown in Figure 11. The numbers refer to the state number readable in the MARCSTATE status register. This register is primarily for test purposes.





19.1 Power-On Start-Up Sequence

When the power supply is turned on, the system must be reset. One of the following two sequences must be followed: Automatic power-on reset (POR) or manual reset.

19.1.1 Automatic POR

A power-on reset circuit is included in the **CC2500**. The minimum requirements stated in Section 4.9 must be followed for the power-on reset to function properly. The internal power-up sequence is completed when CHIP_RDYn goes low. CHIP_RDYn is observed on the SO pin after CSn is pulled low. See Section 10.1 for more details on CHIP_RDYn.

19.1.2 Manual Reset

The other global reset possibility on *CC2500* is the SRES command strobe. By issuing this strobe, all internal registers and states are set to the default, idle state. The manual power-up sequence is as follows (see Figure 12):

- Set SCLK=1 and SI=0, to avoid potential problems with pin control mode (see Section 11.3 on page 23).
- Strobe CSn low / high.
- Hold CSn high for at least 40 µs.
- Pull CSn low and wait for SO to go low (CHIP RDYn).
- Issue the SRES strobe on the SI line.
- When so goes low again, reset is complete and the chip is in the IDLE state.



Figure 12: Power-on reset with SRES

19.2 Crystal Control

The crystal oscillator (XOSC) is either automatically controlled or always on, if MCSM0.XOSC FORCE ON is set.

In the automatic mode, the XOSC will be turned off if the SXOFF or SPWD command strobes are issued; the state machine then goes to XOFF or SLEEP respectively. This can only be done from the IDLE state. The XOSC will be turned off when CSn is released (goes high). The XOSC will be automatically turned on again when CSn goes low. The state machine will then go to the IDLE state. The SO pin on the SPI interface must be zero before the SPI interface is ready to be used; as described in Section 19 on page 20.

If the XOSC is forced on, the crystal will always stay on even in the SLEEP state.

Crystal oscillator start-up time depends on crystal ESR and load capacitances. The electrical specification for the crystal oscillator can be found in Section 4.4 on page 10.

19.3 Voltage Regulator Control

The voltage regulator to the digital core is controlled by the radio controller. When the chip enters the SLEEP state, which is the state with the lowest current consumption, this regulator is disabled. This occurs after CSn is released when a SPWD command strobe has been sent on the SPI interface. The chip is now in the SLEEP state. Setting CSn low again will turn on the regulator and crystal oscillator and make the chip enter the IDLE state.

When wake on radio is enabled, the WOR module will control the voltage regulator as described in Section 19.5.

19.4 Active Modes

CC2500 has two active modes: receive and transmit. These modes are activated directly by the MCU by using the SRX and STX command strobes, or automatically by Wake on Radio.

The frequency synthesizer must be calibrated regularly. **CC2500** has one manual calibration option (using the SCAL strobe), and three automatic calibration options, controlled by the MCSM0.FS_AUTOCAL setting:

- Calibrate when going from IDLE to either RX or TX (or FSTXON)
- Calibrate when going from either RX or TX to IDLE
- Calibrate every fourth time when going from either RX or TX to IDLE

The calibration takes a constant number of XOSC cycles (see Table 28 for timing details).

When RX is activated, the chip will remain in receive mode until a packet is successfully





received or the RX termination timer expires (see Section 19.7). Note: the probability that a false sync word is detected can be reduced by using PQT, CS, maximum sync word length and sync word qualifier mode as describe in Section 17. After a packet is successfully received the radio controller will then go to the state indicated by the MCSM1.RXOFF_MODE setting. The possible destinations are:

- IDLE
- FSTXON: Frequency synthesizer on and ready at the TX frequency. Activate TX with STX.
- TX: Start sending preambles
- RX: Start search for a new packet

Similarly, when TX is active the chip will remain in the TX state until the current packet has been successfully transmitted. Then the state will change as indicated by the MCSM1.TXOFF_MODE setting. The possible destinations are the same as for RX.

The MCU can manually change the state from RX to TX and vice versa by using the command strobes. If the radio controller is currently in transmit and the SRX strobe is used, the current transmission will be ended and the transition to RX will be done.

If the radio controller is in RX when the STX or SFSTXON command strobes are used, the "TX if clear channel" function will be used. If the channel is not clear, the chip will remain in RX. The MCSM1.CCA_MODE setting controls the conditions for clear channel assessment. See Section 17.5 on page 32 for details.

The SIDLE command strobe can always be used to force the radio controller to go to the IDLE state.

19.5 Wake On Radio (WOR)

The optional Wake on Radio (WOR) functionality enables **CC2500** to periodically wake up from deep sleep and listen for incoming packets without MCU interaction.

When WOR is enabled, the *CC2500* will go to the SLEEP state when CSn is released after the SWOR command strobe has been sent on the SPI interface. The RC oscillator must be enabled before the WOR strobe can be used, as it is the clock source for the WOR timer. The on-chip timer will get *CC2500* back into the IDLE state when the timer expires. After a programmable time in RX, the chip goes back to SLEEP, unless a packet is received. See Section 19.7 for details on how the timeout works.

CC2500 can be set up to signal the MCU that a packet has been received by using the GDO pins. If a packet is received, the MCSM1.RXOFF_MODE will determine the behaviour at the end of the received packet. When the MCU has read the packet, it can put the chip back into SLEEP with the SWOR strobe from the IDLE state. The FIFO will lose its contents in the SLEEP state.

The WOR timer has two events, Event 0 and Event 1. In the SLEEP state with WOR activated, reaching Event 0 will turn the digital regulator and start the crystal oscillator. Event 1 follows Event 0 after a programmed timeout.

The time between two consecutive Event 0 is programmed with a mantissa value given by WOREVT1.EVENT0 and WOREVT0.EVENT0, and an exponent value set by WORCTRL.WOR RES. The equation is:

$$t_{Event0} = \frac{750}{f_{XOSC}} \cdot EVENT0 \cdot 2^{5 \cdot WOR_RES}$$

The Event 1 timeout is programmed with WORCTRL.EVENT1. Figure 13 shows the timing relationship between Event 0 timeout and Event 1 timeout.



Figure 13: Event 0 and Event 1 relationship

19.5.1 RC Oscillator and Timing

The frequency of the low-power RC oscillator used for the WOR functionality varies with temperature and supply voltage. In order to




keep the frequency as accurate as possible, the RC oscillator will be calibrated whenever possible, which is when the XOSC is running and the chip is not in the SLEEP state. When the power and XOSC is enabled, the clock used by the WOR timer is a divided XOSC clock. When the chip goes to the sleep state, the RC oscillator will use the last valid calibration result. The frequency of the RC oscillator is locked to the main crystal frequency divided by 750.

19.6 Timing

The radio controller controls most timing in **CC2500**, such as synthesizer calibration, PLL lock and RT/TX turnaround times. Timing from IDLE to RX and IDLE to TX is constant, dependent on the auto calibration setting. RX/TX and TX/RX turnaround times are constant. The calibration time is constant 18739 clock periods. Table 28 shows timing in crystal clock cycles for key state transitions.

Power on time and XOSC start-up times are variable, but within the limits stated in Table 7. Note that in a frequency hopping spread spectrum or a multi-channel protocol the calibration time can be reduced from 721 μ s to approximately 150 μ s. This is explained in Section 30.2.

Description	XOSC periods	26 MHz crystal
Idle to RX, no calibration	2298	88.4 µs
Idle to RX, with calibration	~21037	809 µs
Idle to TX/FSTXON, no calibration	2298	88.4 µs
Idle to TX/FSTXON, with calibration	~21037	809 µs
TX to RX switch	560	21.5 µs
RX to TX switch	250	9.6 µs
RX or TX to IDLE, no calibration	2	0.1 µs
RX or TX to IDLE, with calibration	~18739	721 µs
Manual calibration	~18739	721 µs

 Table 28: State transition timing

19.7 RX Termination Timer

CC2500 has optional functions for automatic termination of RX after a programmable time.

The main use for this functionality is wake-onradio (WOR), but it may be useful for other applications. The termination timer starts when in RX state. The timeout is programmable with the MCSM2.RX_TIME setting. When the timer expires, the radio controller will check the condition for staying in RX; if the condition is not met, RX will terminate. After the timeout, the condition will be checked continuously.

The programmable conditions are:

- MCSM2.RX_TIME_QUAL=0: Continue receive if sync word has been found
- MCSM2.RX_TIME_QUAL=1: Continue receive if sync word has been found or preamble quality is above threshold (PQT)

If the system can expect the transmission to have started when enabling the receiver, the MCSM2.RX_TIME_RSSI function can be used. The radio controller will then terminate RX if the first valid carrier sense sample indicates no carrier (RSSI below threshold). See Section 17.4 on page 31 for details on Carrier Sense.

For OOK modulation, lack of carrier sense is only considered valid after eight symbol periods. Thus, the MCSM2.RX_TIME_RSSI function can be used in OOK mode when the distance between "1" symbols is 8 or less.

If RX terminates due to no carrier sense when the MCSM2.RX_TIME_RSSI function is used, or if no sync word was found when using the MCSM2.RX_TIME timeout function, the chip will always go back to IDLE if WOR is disabled and back to SLEEP if WOR is enabled. Otherwise, the MCSM1.RXOFF_MODE setting determines the state to go to when RX ends.

Note that in wake-on-radio (WOR) mode, the WOR state is cleared in the latter case. This means that the chip will not automatically go back to SLEEP again, even if e.g. the address field in the packet did not match. It is therefore recommended to always wake up the microcontroller on sync word detection when using WOR mode. This can be done by selecting output signal 6 (see Table 33 on page 46) on one of the programmable GDO programming output pins, and the microcontroller to wake up on an edgetriggered interrupt from this GDO pin.



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20 Data FIFO

The **CC2500** contains two 64 byte FIFOs, one for received data and one for data to be transmitted. The SPI interface is used to read from the RX FIFO and write to the TX FIFO. Section 10.4 contains details on the SPI FIFO access. The FIFO controller will detect overflow in the RX FIFO and underflow in the TX FIFO.

When writing to the TX FIFO it is the responsibility of the MCU to avoid TX FIFO overflow. A TX FIFO overflow will result in an error in the TX FIFO content.

Likewise, when reading the RX FIFO the MCU must avoid reading the RX FIFO past its empty value, since an RX FIFO underflow will result in an error in the data read out of the RX FIFO.

The chip status byte that is available on the SO pin while transferring the SPI address contains the fill grade of the RX FIFO if the address is a read operation and the fill grade of the TX FIFO is the address is a write operation. Section 10.1 on page 20 contains more details on this.

The number of bytes in the RX FIFO and TX FIFO can also be read from the status registers RXBYTES.NUM_RXBYTES and TXBYTES.NUM_TXBYTES respectively. If receiving data while reading the last byte in the RX FIFO, the RX FIFO pointer is not updated, resulting in a duplication of the last byte read.

To avoid this problem one should never empty the RX FIFO before the last byte of the packet is received. The following software fix can be used:

- 1. Read RXBYTES.NUM RXBYTES
- 2. If RXBYTES.NUM_RXBYTES < packet length, read RXBYTES.NUM_RXBYTES-1 bytes from the FIFO
- 3. Repeat until RXBYTES.NUM_RXBYTES = number of remaining bytes of the packet
- 4. Read the remaining bytes from the FIFO

The 4-bit FIFOTHR.FIFO_THR setting is used to program threshold points in the FIFOs. Table 29 lists the 16 FIFO_THR settings and

the corresponding thresholds for the RX and TX FIFOs. The threshold value is coded in opposite directions for the RX FIFO and TX FIFO. This gives equal margin to the overflow and underflow conditions when the threshold is reached.

A flag will assert when the number of bytes in the FIFO is equal to or higher than the programmed threshold. The flag is used to generate the FIFO status signals that can be viewed on the GDO pins (see Section 28 on page 45).

Figure 15 shows the number of bytes in both the RX FIFO and TX FIFO when the threshold flag toggles, in the case of FIFO_THR=13. Figure 14 shows the flag as the respective FIFO is filled above the threshold, and then drained below.



Figure 14: FIFO_THR=13 vs. number of bytes in FIFO (GDOx_CFG=0x00 in Rx and GDOx_CFG=0x02 in Tx)

FIFO_THR	Bytes in TX FIFO	Bytes in RX FIFO
0 (0000)	61	4
1 (0001)	57	8
2 (0010)	53	12
3 (0011)	49	16
4 (0100)	45	20
5 (0101)	41	24
6 (0110)	37	28
7 (0111)	33	32
8 (1000)	29	36
9 (1001)	25	40
10 (1010)	21	44
11 (1011)	17	48
12 (1100)	13	52
13 (1101)	9	56
14 (1110)	5	60
15 (1111)	1	64

Table 29: FIFO_THR settings and the corresponding FIFO thresholds

TEXAS INSTRUMENTS





Figure 15: Example of FIFOs at threshold

21 Frequency Programming

The frequency programming in *CC2500* is designed to minimize the programming needed in a channel-oriented system.

To set up a system with channel numbers, the desired channel spacing is programmed with the MDMCFG0.CHANSPC_M and MDMCFG1.CHANSPC_E registers. The channel spacing registers are mantissa and exponent respectively.

The base or start frequency is set by the 24 bit frequency word located in the FREQ2, FREQ1 and FREQ0 registers. This word will typically be set to the centre of the lowest channel frequency that is to be used.

The desired channel number is programmed with the 8-bit channel number register, CHANNR.CHAN, which is multiplied by the channel offset. The resultant carrier frequency is given by:

$$f_{carrier} = \frac{f_{XOSC}}{2^{16}} \cdot \left(FREQ + CHAN \cdot \left((256 + CHANSPC _M) \cdot 2^{CHANSPC _E-2} \right) \right)$$

With a 26 MHz crystal the maximum channel spacing is 405 kHz. To get e.g. 1 MHz channel spacing one solution is to use 333 kHz channel spacing and select each third channel in CHANNR.CHAN.

The preferred IF frequency is programmed with the FSCTRL1.FREQ_IF register. The IF frequency is given by:

$$f_{IF} = \frac{f_{XOSC}}{2^{10}} \cdot FREQ_IF$$

Note that the SmartRF[®] Studio software automatically calculates the optimum FSCTRL1.FREQ_IF register setting based on channel spacing and channel filter bandwidth.

If any frequency programming register is altered when the frequency synthesizer is running, the synthesizer may give an undesired response. Hence, the frequency programming should only be updated when the radio is in the IDLE state.





22 VCO

The VCO is completely integrated on-chip.

22.1 VCO and PLL Self-Calibration

The VCO characteristics will vary with temperature and supply voltage changes, as well as the desired operating frequency. In order to ensure reliable operation, **CC2500** includes frequency synthesizer self-calibration circuitry. This calibration should be done regularly, and must be performed after turning on power and before using a new frequency (or channel). The number of XOSC cycles for completing the PLL calibration is given in Table 28 on page 37.

23 Voltage Regulators

CC2500 contains several on-chip linear voltage regulators, which generate the supply voltage needed by low-voltage modules. These voltage regulators are invisible to the user, and can be viewed as integral parts of the various modules. The user must however make sure that the absolute maximum ratings and required pin voltages in Table 1 and Table 13 are not exceeded. The voltage regulator for the digital core requires one external decoupling capacitor.

Setting the CSn pin low turns on the voltage regulator to the digital core and starts the crystal oscillator. The SO pin on the SPI interface must go low before using the serial interface (setup time is given in Table 16).

24 Output Power Programming

The RF output power level from the device has two levels of programmability, as illustrated in Figure 16. Firstly, the special PATABLE register can hold up to eight user selected output power settings. Secondly, the 3-bit FRENDO.PA POWER value selects the PATABLE entry to use. This two-level functionality provides flexible PA power ramp up and ramp down at the start and end of transmission. All the PA power settings in the PATABLE from index 0 up to the FRENDO.PA POWER value are used.

The calibration can be initiated automatically or manually. The synthesizer can be automatically calibrated each time the synthesizer is turned on, or each time the synthesizer is turned off. This is configured with the MCSMO.FS_AUTOCAL register setting. In manual mode, the calibration is initiated when the SCAL command strobe is activated in the IDLE mode.

Note that the calibration values are maintained in sleep mode, so the calibration is still valid after waking up from sleep mode (unless supply voltage or temperature has changed significantly).

If the chip is programmed to enter power-down mode, (SPWD strobe issued), the power will be turned off after CSn goes high. The power and crystal oscillator will be turned on again when CSn goes low.

The voltage regulator output should only be used for driving the *CC2500*.

The power ramping at the start and at the end of a packet can be turned off by setting FRENDO.PA_POWER to zero and then program the desired output power to index zero in the PATABLE.

Table 31 contains recommended PATABLEsettings for various output levels andfrequency bands. See Section 10.5 on page22 for PATABLE programming details.

PATABLE must be programmed in burst mode if you want to write to other entries than PATABLE[0].





Figure 16: PA_POWER and PATABLE

Default power setting	Output power, typical [dBm]	Current consumption, typical [mA]	
0xC6	-11.8	11.1	

Table 30: Output power and current consumption for default PATABLE setting

Output power, typical, +25°C, 3.0 V [dBm]	PATABLE value	Current consumption, typical [mA]
(–55 or less)	0x00	8.4
-30	0x50	9.9
-28	0x44	9.7
-26	0xC0	10.2
-24	0x84	10.1
-22	0x81	10.0
-20	0x46	10.1
-18	0x93	11.7
-16	0x55	10.8
-14	0x8D	12.2
-12	0xC5	11.1
-10	0x97	12.2
-8	0x6E	14.1
-6	0x7F	15.1
-4	0xA9	16.2
-2	0xBB	17.7
0	0xFE	21.2
1.5	0xFF	21.5

Table 31: Optimum PATABLE settings for various output power levels (subject to changes)

Chipcon Products from Texas Instruments



25 Selectivity Graphs

Figure 17 to Figure 21 show the typical selectivity performance (adjacent and alternate rejection).



Figure 17: Typical selectivity at 2.4 kbps. IF frequency is 273.9 kHz. MDMCFG2.DEM_DCFILT_OFF = 1



Figure 18: Typical selectivity at 10 kbps. IF frequency is 273.9 kHz. MDMCFG2.DEM_DCFILT_OFF = 1





Figure 19: Typical selectivity at 250 kbps. IF frequency is 177.7 kHz. MDMCFG2.DEM_DCFILT_OFF = 0



Figure 20: Typical selectivity at 250 kbps. IF frequency is 457 kHz. MDMCFG2.DEM_DCFILT_OFF = 1



Figure 21: Typical selectivity at 500 kbps. IF frequency is 307.4 kHz. MDMCFG2.DEM_DCFILT_OFF = 0







26 Crystal Oscillator

A crystal in the frequency range 26-27 MHz must be connected between the XOSC_Q1 and XOSC_Q2 pins. The oscillator is designed for parallel mode operation of the crystal. In addition, loading capacitors (C81 and C101) for the crystal are required. The loading capacitor values depend on the total load capacitance, C_L , specified for the crystal. The total load capacitance seen between the crystal terminals should equal C_L for the crystal to oscillate at the specified frequency.

$$C_L = \frac{1}{\frac{1}{C_{81}} + \frac{1}{C_{101}}} + C_{parasitic}$$

The parasitic capacitance is constituted by pin input capacitance and PCB stray capacitance. Total parasitic capacitance is typically 2.5 pF.

The crystal oscillator circuit is shown in Figure 22. Typical component values for different values of C_{L} are given in Table 32.

The crystal oscillator is amplitude regulated. This means that a high current is used to start up the oscillations. When the amplitude builds up, the current is reduced to what is necessary to maintain approximately 0.4Vpp signal swing. This ensures a fast start-up, and keeps the drive level to a minimum. The ESR of the crystal should be within the specification in order to ensure a reliable start-up (see Section 4.4 on page 10).

The initial tolerance, temperature drift, aging and load pulling should be carefully specified in order to meet the required frequency accuracy in a certain application. By specifying the *total* expected frequency accuracy in SmartRF[®] Studio together with data rate and frequency deviation, the software calculates the total bandwidth and compares this to the chosen receiver channel filter bandwidth. The software reports any contradictions, and a more accurate crystal is recommended if required.



Figure 22: Crystal oscillator circuit

Component	C _L = 10 pF	С _L =13 рF	C _L =16 pF
C81	15 pF	22 pF	27 pF
C101	15 pF	22 pF	27 pF

Table 32: Crys	stal oscillator component values
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26.1 Reference Signal

The chip can alternatively be operated with a reference signal from 26 to 27 MHz instead of a crystal. This input clock can either be a full-swing digital signal (0 V to VDD) or a sine wave of maximum 1 V peak-peak amplitude. The reference signal must be connected to the

XOSC_Q1 input. The sine wave must be connected to XOSC_Q1 using a serial capacitor. The XOSC_Q2 line must be left unconnected. C81 and C101 can be omitted when using a reference signal.



||||2+5|||||

27 External RF Match

The balanced RF input and output of **CC2500** share two common pins and are designed for a simple, low-cost matching and balun network on the printed circuit board. The receive- and transmit switching at the **CC2500** front-end is controlled by a dedicated on-chip function, eliminating the need for an external RX/TX-switch.

A few passive external components combined with the internal RX/TX switch/termination circuitry ensures match in both RX and TX mode. Although **CC2500** has a balanced RF input/output, the chip can be connected to a single-ended antenna with few external low cost capacitors and inductors.

The passive matching/filtering network connected to *CC2500* should have the following differential impedance as seen from the RF-port (RF_P and RF_N) towards the antenna:

 Z_{out} = 80 + j74 Ω

28 General Purpose / Test Output Control Pins

The three digital output pins GDO0, GDO1 and GDO2 are general control pins configured with IOCFG0.GDO0_CFG, IOCFG1.GDO1_CFG and IOCFG2.GDO3_CFG respectively. Table 33 shows the different signals that can be monitored on the GDO pins. These signals can be used as an interrupt to the MCU. GDO1 is the same pin as the SO pin on the SPI interface, thus the output programmed on this pin will only be valid when CSn is high. The default value for GDO1 is 3-stated, which is useful when the SPI interface is shared with other devices.

The default value for GDO0 is a 135-141 kHz clock output (XOSC frequency divided by 192). Since the XOSC is turned on at power-on-reset, this can be used to clock the MCU in systems with only one crystal. When the MCU is up and running, it can change the clock frequency by writing to IOCFG0.GDO0 CFG.

An on-chip analog temperature sensor is enabled by writing the value 128 (0x80h) to the IOCFG0.GDO0_CFG register. The voltage on the GDO0 pin is then proportional to temperature. See Section 4.7 on page 12 for temperature sensor specifications.





cbcc2 credits credits 0 (xx00) Associated to the RX FIFO is senset; when RX FIFO is filled above RXFIFO_THR or the end of packet is reached. De- associated to the RX FIFO Asserts when RX FIFO is filled above RXFIFO_THR. De-asserts when the TX FIFO is associated to the TX FIFO. Asserts when the TX FIFO is filled above RXFIFO_THR. De-asserts when the TX FIFO is associated to the TX FIFO. Asserts when the TX FIFO is full. De-asserts when the TX FIFO is drained below 2 (0x02) Associated to the TX FIFO. Asserts when TX FIFO is full. De-asserts when the TX FIFO is drained below 4 (0x04) Associated to the TX FIFO Asserts when the TX FIFO is full. 5 (0x05) Asserts when the TX FIFO has underflowed. De-asserts when the FIFO is flushed. 5 (0x06) Clear channel asserts and the flux associated in the RX FIFO oxer the programmed PD value. 6 (0x06) Clear channel assessment. High when RSSI level is below the programmed PD value. 9 (0x07) Clear channel assessment. High when RSSI level is below the programmed PD value. 9 (0x06) Clear channel assessment. High when RSSI level is below the bread on the current CCA. MODE setting 10 (0x0A) 10 (0x0A) Cock detector orupit 11 (0x0B) Serial Clock Synchronous to the data in synchronous serial mode. 12 (0x0C) Clear is setup on the data in synchronous serial mode. 13 (0x0D) Serial transparent Dava Uput.	GDO0_CF GDO1_CF	G[5:0] Description
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15 (0x0F) Reserved – used for test. 17 (0x11) Reserved – used for test. 17 (0x13) Reserved – used for test. 18 (0x12) Reserved – used for test. 19 (0x13) Reserved – used for test. 20 (0x14) Reserved – used for test. 21 (0x15) Reserved – used for test. 22 (0x16) Reserved – used for test. 22 (0x17) RX HARD DATA[0]. Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 22 (0x16) Reserved – used for test. 25 (0x17) Rx HARD DatA[0]. Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 25 (0x17) Reserved – used for test. 27 (0x18) PA_PD-PA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 28 (0x1C) LNA PD_LDNA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 29 (0x20) RX SYMBOL_TICK. Can be used together with RX_HARD_DATA for alternative serial RX output. 20 (0x11) Reserved – used for test. 31 (0x1F) Reserved – used for test. 33 (0x21) Reserved – used for test. 33 (0x22) Reserved – used for test. 33 (0x22) Reserved – used for test.	13 (0x0D)	Serial transparent Data Output. Used for asynchronous serial mode.
16 (bx10) Reserved - used for test. 17 (bx11) Reserved - used for test. 18 (bx12) Reserved - used for test. 20 (bx14) Reserved - used for test. 21 (bx15) Reserved - used for test. 22 (bx16) RX HARD DATA[1) Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 23 (bx17) RX HARD DATA[1) Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 24 (bx18) Reserved - used for test. 25 (bx19) Reserved - used for test. 26 (bx14) Reserved - used for test. 26 (bx16) Reserved - used for test. 27 (bx18) Reserved - used for test. 28 (bx10) LNA FPD LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RXTX switch. 29 (bx10) RX SYMBOL_TICK. Can be used together with RX HARD DATA for alternative serial RX output. 30 (bx16) Reserved - used for test. 31 (bx17) Reserved - used for test. 32 (bx20) Reserved - used for test. 33 (bx21) Reserved - used for test. 33 (bx22) Reserved - used for test. 33 (bx22) Reserved - used for test. 33 (bx22) Reserved - used fo		
17 Reserved - used for test. 19 Rix (X) Reserved - used for test. 20 Rix (A) Reserved - used for test. 21 Rix (A) Reserved - used for test. 22 Rix (A) Reserved - used for test. 23 Rix (A) Reserved - used for test. 24 Rix (A) Reserved - used for test. 25 Rix (A) Reserved - used for test. 26 Rix (A) Reserved - used for test. 26 Rix (A) Reserved - used for test. 26 Rix (A) Reserved - used for test. 27 INX (A) Reserved - used for test. 28 Rix (A) Reserved - used for test. 29 Rix (A) Reserved - used for test. 20 Rix (A) Rix (A) 20 Rix (A) Reserved - used for test. 30 Rix (A) Reserved - used for test. 31 Reserved - used for test. Reserved - used for test. 31 Reserved - used for test. Reserved - used for test. 31 Reserved - used for test. Reserved - used for test.		
19 Reserved - used for test. 21 (0x14) Reserved - used for test. 22 (0x15) Reserved - used for test. 23 (0x17) RX HARD DATA(1). Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 23 (0x16) Reserved - used for test. 25 (0x16) Reserved - used for test. 26 (0x16) Reserved - used for test. 27 (0x18) Reserved - used for test. 26 (0x10) Reserved - used for test. 27 (0x18) PA PD: PA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 28 (0x10) RX SYMBOL_TICK. Can be used together with RX HARD DATA for alternative serial RX output. 30 (0x11) Reserved - used for test. 30 31 (0x12) Reserved - used for test. 31 32 (0x20) Reserved - used for test. 32 33 (0x21) Reserved - used for test. 33 33 (0x22) Reserved - used for test. 33 33 (0x24) Reserved - used for test. 33 33 (0x26	17 (0x11)	Reserved – used for test.
120 (DX14) Reserved - used for test. 121 (DX15) Reserved - used for test. 122 (DX16) RX HARD DATA[0]. Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 123 (DX17) Reserved - used for test. 126 (DX16) Reserved - used for test. 126 (DX17) Reserved - used for test. 126 (DX17) Reserved - used for test. 126 (DX17) Reserved - used for test. 127 (DX18) PA PD. PA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 128 (DX1C) INA PD. DA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 128 (DX1C) INA PD. DA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 129 (DX1D) RX SYMBOL_TICK. Can be used together with RX HARD_DATA for alternative serial RX output. 30 (DX1F) Reserved - used for test. 31 (DX1F) Reserved - used for test. 33 (DX21) Reserved - used for test. 33 (DX22) Reserved - used for test. 33 (DX23) Reserved - used for test. 33 (DX25) Reserved - used for test. 34 (DX22) Reserved - used for test. 35 (DX26) R		
11 (DX15) Reserved - used for test. 22 (DX16) RX HARD DATA(1) Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 23 (DX16) RX HARD DATA(1) Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 24 (DX18) Reserved - used for test. 25 (DX19) Reserved - used for test. 26 (DX17) RX symbol. 27 (DX18) Reserved - used for test. 28 (DX17) LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 28 (DX17) LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 29 (DX10) RX SYMBOL_TICK. Can be used together with RX HARD_DATA for alternative serial RX output. 30 (DX17) Reserved - used for test. 31 (DX17) Reserved - used for test. 32 (DX20) Reserved - used for test. 33 (DX21) Reserved - used for test. 34 (DX22) Reserved - used for test. 35 (DX23) Reserved - used for test. 36 (DX24) Reserved - used for test. 37 (DX25) Reserved - used for test. 38 (DX26) Reserved - used for test. 39 (DX27) Reserved - used for test.		
23 (0x17) RX_HARD_DATA[0]. Can be used together with RX_SYMBOL_TICK for alternative serial RX output. 24 (0x18) Reserved - used for test. 25 (0x17) Reserved - used for test. 27 (0x18) PA_PD_PA is enabled when 0, in power-down when 1. Can be used to control external PA or RX/TX switch. 28 (0x17) Reserved - used for test. 29 (0x10) RX_SYMBOL_TICK. Can be used together with RX_HARD_DATA for alternative serial RX output. 30 (0x11) Reserved - used for test. 31 (0x11) Reserved - used for test. 32 (0x20) Reserved - used for test. 33 (0x21) Reserved - used for test. 33 (0x22) Reserved - used for test. 33 (0x24) Reserved - used for test. 33 (0x27) Reserved - used for test. 33 (0x27) Reserved - used for test. 34 (0x28) Reserved - used for test. 34 (0x29) Reserved - used for test. 34 (0x20) Reserved - used for test. 34 (0x22) Reserved - used for test. 35 (0x21) Reserved - used for test. 36 (0x22) Chalp Reserved - used for test. 37 (0x25) Reserved - used for test. 30 (0x27)		
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25 (0x19) Reserved - used for test. 26 (0x1A) Reserved - used for test. 27 (0x1B) PA PD. PA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 28 (0x1C) LNA PD. LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 28 (0x1C) RX SYMBOL TICK. Can be used together with RX HARD DATA for alternative serial RX output. 30 (0x1E) Reserved - used for test. 31 (0x1F) Reserved - used for test. 32 (0x20) Reserved - used for test. 33 (0x21) Reserved - used for test. 33 (0x22) Reserved - used for test. 39 (0x27) Reserved - used for test. 39 (0x27) Reserved - used for test. 40 (0x28) Reserved - used for test. 41 (0x29) Chestred for test. 42 (0x20) Reserved - used for test. 43 (0x21) Reserved - used for test. 44 (0x22) CR		
27 (0x1B) PA. PD. PA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 28 (0x1C) LNA PD. LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 29 (0x1D) RX SYMBOL TICK. Can be used together with RX HARD_DATA for alternative serial RX output. 30 (0x1E) Reserved - used for test. 31 (0x1F) Reserved - used for test. 32 (0x20) Reserved - used for test. 33 (0x21) Reserved - used for test. 34 (0x22) Reserved - used for test. 35 (0x23) Reserved - used for test. 36 (0x24) Reserved - used for test. 37 (0x25) Reserved - used for test. 38 (0x26) Reserved - used for test. 39 (0x27) Reserved - used for test. 41 (0x29) CHIP RDY 42 (0x2A) Reserved - used for test. 43 (0x25) Reserved - used for test. 43 (0x26) CENN. When this output is 0, GDO0 is configured as input (for serial TX data). 44 (0x2C) Reserved - used for test. 43 (0x25) CENN. When this output is 0, GDO0 is configured as input (for serial TX data). 46 (0x30)	25 (0x19)	Reserved – used for test.
28 (0x1C) LNA PD. LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch. 29 (0x1D) RX SYMBOL TICK. Can be used together with RX_HARD_DATA for alternative serial RX output. 30 (0x1E) Reserved - used for test. 31 (0x1F) Reserved - used for test. 32 (0x20) Reserved - used for test. 33 (0x21) Reserved - used for test. 34 (0x22) Reserved - used for test. 35 (0x23) Reserved - used for test. 36 (0x24) Reserved - used for test. 37 (0x25) Reserved - used for test. 38 (0x26) Reserved - used for test. 39 (0x27) Reserved - used for test. 40 (0x28) Reserved - used for test. 41 (0x24) Reserved - used for test. 42 (0x2A) Reserved - used for test. 43 (0x25) Reserved - used for test. 44 (0x26) GDOO_Z Z IN IN. When this output is 0, GDOO is configured as input (for serial TX data). 46 (0x25) High impedance (3-state) 47 (0x27) HW to (HW1 achieved with _INV signal) 48 (0x30) CLK XOSC/15 50 (0x32) CLK XOSC/2 <th></th> <th></th>		
29 (0x1D) RX. SYMBOL_TICK. Can be used together with RX_HARD_DATA for alternative serial RX output. 30 (0x1F) Reserved – used for test. 31 (0x1F) Reserved – used for test. 32 (0x20) Reserved – used for test. 33 (0x21) Reserved – used for test. 34 (0x22) Reserved – used for test. 35 (0x23) Reserved – used for test. 36 (0x24) Reserved – used for test. 37 (0x25) Reserved – used for test. 38 (0x26) Reserved – used for test. 39 (0x27) Reserved – used for test. 39 (0x27) Reserved – used for test. 40 (0x28) Reserved – used for test. 41 (0x29) CHIP RDY 42 (0x2A) Reserved – used for test. 43 (0x20) GDO0_Z_STABLE 44 (0x2C) Reserved – used for test. 43 (0x21) GDO0_Z_STABLE 44 (0x22) GDO0_Z_STABLE 44 (0x22) GDO0_Z_STABLE 44 (0x22) GDO0_Z_STABLE 47 (0x25) High impedance (3-state) 47 (0x25) High impedance (3-state)		LNA PD. LNA is enabled when 0, in power-down when 1. Can be used to control external LNA or RX/TX switch.
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47 (0x2F) HW to 0 (HW1 achieved with _INV signal) 48 (0x30) CLK_XOSC/1 49 (0x31) CLK_XOSC/1.5 50 (0x32) CLK_XOSC/2 51 (0x33) CLK_XOSC/3 52 (0x34) CLK_XOSC/4 53 (0x35) CLK_XOSC/6 54 (0x36) CLK_XOSC/12 56 (0x38) CLK_XOSC/12 56 (0x38) CLK_XOSC/16 57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/48 60 (0x3C) CLK_XOSC/48 60 (0x3C) CLK_XOSC/48 61 (0x3D) CLK_XOSC/128		
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50 (0x32) CLK_XOSC/2 51 (0x33) CLK_XOSC/3 52 (0x34) CLK_XOSC/4 53 (0x35) CLK_XOSC/6 54 (0x36) CLK_XOSC/8 55 (0x37) CLK_XOSC/12 56 (0x38) CLK_XOSC/16 57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/32 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/128		
51 (0x33) CLK_XOSC/3 52 (0x34) CLK_XOSC/4 53 (0x35) CLK_XOSC/6 54 (0x36) CLK_XOSC/8 55 (0x37) CLK_XOSC/12 56 (0x38) CLK_XOSC/16 57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/24 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/128		
52 (0x34) CLK_XOSC/4 53 (0x35) CLK_XOSC/6 54 (0x36) CLK_XOSC/8 55 (0x37) CLK_XOSC/12 56 (0x38) CLK_XOSC/16 57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/24 59 (0x3B) CLK_XOSC/32 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/128	51 (0x33)	CLK_XOSC/3
54 (0x36) CLK_XOSC/8 55 (0x37) CLK_XOSC/12 56 (0x38) CLK_XOSC/16 57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/24 59 (0x3B) CLK_XOSC/32 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/128		
55 (0x37) CLK_XOSC/12 56 (0x38) CLK_XOSC/16 57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/32 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/128		
57 (0x39) CLK_XOSC/24 58 (0x3A) CLK_XOSC/32 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/96 62 (0x3E) CLK_XOSC/128	55 (0x37)	CLK_XOSC/12
58 (0x3A) CLK_XOSC/32 59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/96 62 (0x3E) CLK_XOSC/128		
59 (0x3B) CLK_XOSC/48 60 (0x3C) CLK_XOSC/64 61 (0x3D) CLK_XOSC/96 62 (0x3E) CLK_XOSC/128		
61 (0x3D) CLK_XOSC/96 62 (0x3E) CLK_XOSC/128	59 (0x3B)	CLK_XOSC/48
62 (0x3E) CLK_XOSC/128		

Table 33: GDO signal selection



29 Asynchronous and Synchronous Serial Operation

Several features and modes of operation have been included in the **CC2500** to provide backward compatibility with previous Chipcon products and other existing RF communication systems. For new systems, it is recommended to use the built-in packet handling features, as they can give more robust communication, significantly offload the microcontroller and simplify software development.

29.1 Asynchronous operation

For backward compatibility with systems already using the asynchronous data transfer from other Chipcon products, asynchronous transfer is also included in *CC2500*. When asynchronous transfer is enabled, several of the support mechanisms for the MCU that are included in *CC2500* will be disabled, such as packet handling hardware, buffering in the FIFO and so on. The asynchronous transfer mode does not allow the use of the data whitener, interleaver and FEC.

Only 2-FSK, GFSK and OOK are supported for asynchronous transfer.

Setting PKTCTRL0.PKT_FORMAT to 3 enables asynchronous transparent (serial) mode.

In TX, the GDO0 pin is used for data input (TX data). Data output can be GDO0, GDO1 or GDO2.

The MCU must control start and stop of transmit and receive with the STX, SRX and SIDLE strobes.

The **CC2500** modulator samples the level of the asynchronous input 8 times faster than the programmed data rate. The timing requirement for the asynchronous stream is that the error in the bit period must be less than one eighth of the programmed data rate.

29.2 Synchronous serial operation

Setting PKTCTRL0.PKT FORMAT to 1 enables synchronous serial operation mode. In the synchronous serial operation mode, data is transferred on a two wire serial interface. The **CC2500** provides a clock that is used to set up new data on the data input line or sample data on the data output line. Data input (TX data) is the GDOO pin. This pin will automatically be configured as an input when TX is active. The data output pin can be any of the GDO pins; this is set by the IOCFG0.GDO0 CFG, IOCFG1.GDO1 CFG and IOCFG2.GDO2 CFG fields.

Preamble and sync word insertion/detection may or may not be active, dependent on the sync mode set by the MDMCFG2.SYNC_MODE. If preamble and sync word is disabled, all other packet handler features and FEC should also be disabled. The MCU must then handle preamble and sync word insertion and detection in software. If preamble and sync word insertion/detection is left on, all packet handling features and FEC can be used. The **CC2500** will insert and detect the preamble and sync word and the MCU will only provide/get the data payload. This is equivalent to the recommended FIFO operation mode.

30 System considerations and Guidelines

30.1 SRD Regulations

International regulations and national laws regulate the use of radio receivers and transmitters. Short Range Devices (SRDs) for license free operation are allowed to operate in the 2.45 GHz bands worldwide. The most important regulations are EN 300 440 and EN 300 328 (Europe), FCC CFR47 part 15.247 and 15.249 (USA), and ARIB STD-T66 (Japan). A summary of the most important aspects of these regulations can be found in Application Note *AN032 SRD regulations for license-free transceiver operation in the 2.4*

GHz band, available from the Chipcon website.

Please note that compliance with regulations is dependent on complete system performance. It is the customer's responsibility to ensure that the system complies with regulations.

30.2 Frequency Hopping and Multi-Channel Systems

The 2.400 – 2.4835 GHz band is shared by many systems both in industrial, office and





home environments. It is therefore recommended to use frequency hopping spread spectrum (FHSS) or a multi-channel protocol because the frequency diversity makes the system more robust with respect to interference from other systems operating in the same frequency band. FHSS also combats multipath fading.

CC2500 is highly suited for FHSS or multichannel systems due to its agile frequency synthesizer and effective communication interface. Using the packet handling support and data buffering is also beneficial in such systems as these features will significantly offload the host controller.

Charge pump current, VCO current and VCO capacitance array calibration data is required for each frequency when implementing frequency hopping for *CC2500*. There are 3 ways of obtaining the calibration data from the chip:

1) Frequency hopping with calibration for each hop. The PLL calibration time is approximately 720 μ s.

2) Fast frequency hopping without calibration for each hop can be done by calibrating each frequency at startup and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values in MCU memory. Between each frequency hop, the calibration process can then be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency. The PLL turn on time is approximately 90 µs.

3) Run calibration on a single frequency at startup. Next write Ohex to FSCAL3[5:4] to disable the charge pump calibration. After writing to FSCAL3[5:4] strobe SRX (or STX) with MCSM0.FS_AUTOCAL = 1 for each new frequency hop. That is, VCO current and VCO capacitance calibration is done but not charge pump current calibration. When charge pump current calibration is disabled the calibration time is reduced from approximately 720 µs to approximately 150 µs.

There is a trade off between blanking time and memory space needed for storing calibration data in non-volatile memory. Solution 2) above gives the shortest blanking interval, but requires more memory space to store calibration values. Solution 3) gives approximately 570 µs smaller blanking interval than solution 1).

30.3 Data Burst Transmissions

The high maximum data rate of **CC2500** opens up for burst transmissions. A low average data rate link (say 10 kbps), can be realized using a higher over-the-air data rate. Buffering the data and transmitting in bursts at high data rate (say 500 kbps) will reduce the time in active mode, and hence also reduce the average current consumption significantly. Reducing the time in active mode will reduce the likelihood of collisions with other systems, e.g. WLAN.

30.4 Continuous Transmissions

In data streaming applications the **CC2500** opens up for continuous transmissions at 500 kbps effective data rate. As the modulation is done with an I/Q up-converter with LO I/Qsignals coming from a closed loop PLL, there is no limitation in the length of a transmission. (Open loop modulation used in some transceivers often prevents this kind of continuous data streaming and reduces the effective data rate.)

30.5 Crystal Drift Compensation

The **CC2500** has a very fine frequency resolution (see Table 9). This feature can be used to compensate for frequency offset and drift.

The frequency offset between an 'external' transmitter and the receiver is measured in the **CC2500** and can be read back from the FREQEST status register as described in Section 14.1. The measured frequency offset can be used to calibrate the frequency using the 'external' transmitter as the reference. That is, the received signal of the device will match the receiver's channel filter better. In the same way the centre frequency of the transmitted signal will match the 'external' transmitter's signal.

30.6 Spectrum Efficient Modulation

CC2500 also has the possibility to use Gaussian shaped FSK (GFSK). This spectrum-shaping feature improves adjacent channel power (ACP) and occupied bandwidth. In 'true' FSK systems with abrupt frequency shifting, the spectrum is inherently broad. By making the frequency shift 'softer', the spectrum can be made significantly narrower. Thus, higher data rates can be

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transmitted in the same bandwidth using GFSK.

30.7 Low Cost Systems

As the *CC2500* provides 500 kbps multichannel performance without any external filters, a very low cost system can be made.

A differential antenna will eliminate the need for a balun, and the DC biasing can be achieved in the antenna topology, see Figure 3.

A HC-49 type SMD crystal is used in the CC2500EM reference design. Note that the crystal package strongly influences the price. In a size constrained PCB design a smaller, but more expensive, crystal may be used.

30.8 Battery Operated Systems

In low power applications, the SLEEP state with the crystal oscillator core switched off should be used when the **CC2500** is not active. It is possible to leave the crystal oscillator core running in the SLEEP state if start-up time is critical.

The WOR functionality should be used in low power applications.

30.9 Increasing Output Power

In some applications it may be necessary to extend the link range. Adding an external power amplifier is the most effective way of doing this.

The power amplifier should be inserted between the antenna and the balun, and two T/R switches are needed to disconnect the PA in RX mode. See Figure 23.





31 Configuration Registers

The configuration of **CC2500** is done by programming 8-bit registers. The configuration data based on selected system parameters are most easily found by using the SmartRF[®] Studio software. Complete descriptions of the registers are given in the following tables. After chip reset, all the registers have default values as shown in the tables.

There are 14 Command Strobe Registers, listed in Table 34. Accessing these registers will initiate the change of an internal state or mode. There are 47 normal 8-bit Configuration Registers, listed in Table 35. Many of these

registers are for test purposes only, and need not be written for normal operation of *CC2500*.

There are also 12 Status registers, which are listed in Table 36. These registers, which are read-only, contain information about the status of *CC2500*.

The two FIFOs are accessed through one 8-bit register. Write operations write to the TX FIFO, while read operations read from the RX FIFO.

During the address transfer and while writing to a register or the TX FIFO, a status byte is





returned. This status byte is described in Table 17 on page 21.

Table 37 summarizes the SPI address space. The address to use is given by adding the base address to the left and the burst and read/write bits on the top. Note that the burst bit has different meaning for base addresses above and below 0x2F.

Address	Strobe Name	Description		
0x30	SRES	Reset chip.		
0x31	SFSTXON	Enable and calibrate frequency synthesizer (if MCSM0 . FS_AUTOCAL=1). If in RX (with CCA): Go to a wait state where only the synthesizer is running (for quick RX / TX turnaround).		
0x32	SXOFF	Turn off crystal oscillator.		
0x33	SCAL	Calibrate frequency synthesizer and turn it off (enables quick start). SCAL can be strobed in IDLE state without setting manual calibration mode (MCSM0.FS_AUTOCAL=0)		
0x34	SRX	Enable RX. Perform calibration first if coming from IDLE and MCSM0 . FS_AUTOCAL=1.		
0x35	STX	In IDLE state: Enable TX. Perform calibration first if MCSM0 . FS_AUTOCAL=1. If in RX state and CCA is enabled: Only go to TX if channel is clear.		
0x36	SIDLE	Exit RX / TX, turn off frequency synthesizer and exit Wake-On-Radio mode if applicable.		
0x38	SWOR	Start automatic RX polling sequence (Wake-on-Radio) as described in Section 19.5.		
0x39	SPWD	Enter power down mode when CSn goes high.		
0x3A	SFRX	Flush the RX FIFO buffer. Only issue in IDLE, TXFIFO_UNDERFLOW or RXFIFO_OVERFLOW states.		
0x3B	SFTX	Flush the TX FIFO buffer. Only issue in IDLE, TXFIFO_UNDERFLOW or RXFIFO_OVERFLOW states.		
0x3C	SWORRST	Reset real time clock.		
0x3D	SNOP	No operation. May be used to pad strobe commands to two bytes for simpler software.		

 Table 34: Command Strobes



Address	ess Register Description		Preserved in SLEEP state	Details on page number
0x00	IOCFG2	GDO2 output pin configuration	Yes	54
0x01	IOCFG1	GDO1 output pin configuration	Yes	54
0x02	IOCFG0	GDO0 output pin configuration	Yes	54
0x03	FIFOTHR	RX FIFO and TX FIFO thresholds	Yes	55
0x04	SYNC1	Sync word, high byte	Yes	55
0x05	SYNC0	Sync word, low byte	Yes	55
0x06	PKTLEN	Packet length	Yes	55
0x07	PKTCTRL1	Packet automation control	Yes	56
0x08	PKTCTRL0	Packet automation control	Yes	57
0x09	ADDR	Device address	Yes	57
0x0A	CHANNR	Channel number	Yes	57
0x0B	FSCTRL1	Frequency synthesizer control	Yes	58
0x0C	FSCTRL0	Frequency synthesizer control	Yes	58
0x0D	FREQ2	Frequency control word, high byte	Yes	58
0x0E	FREQ1	Frequency control word, middle byte	Yes	58
0x0F	FREQ0	Frequency control word, low byte	Yes	58
0x10	MDMCFG4	Modem configuration	Yes	59
0x11	MDMCFG3	Modem configuration	Yes	59
0x12	MDMCFG2	Modem configuration	Yes	60
0x13	MDMCFG1	Modem configuration	Yes	61
0x14	MDMCFG0	Modem configuration	Yes	61
0x15	DEVIATN	Modem deviation setting	Yes	62
0x16	MCSM2	Main Radio Control State Machine configuration	Yes	62
0x17	MCSM1	Main Radio Control State Machine configuration	Yes	63
0x18	MCSM0	Main Radio Control State Machine configuration	Yes	64
0x19	FOCCFG	Frequency Offset Compensation configuration	Yes	64
0x1A	BSCFG	Bit Synchronization configuration	Yes	64
0x1B	AGCTRL2	AGC control	Yes	65
0x1C	AGCTRL1	AGC control	Yes	66
0x1D	AGCTRL0	AGC control	Yes	66
0x1E	WOREVT1	High byte Event 0 timeout	Yes	66
0x1F	WOREVT0	Low byte Event 0 timeout	Yes	67
0x20	WORCTRL	Wake On Radio control	Yes	67
0x21	FREND1	Front end RX configuration	Yes	67
0x22	FREND0	Front end TX configuration	Yes	68
0x23	FSCAL3	Frequency synthesizer calibration	Yes	68
0x24	FSCAL2	Frequency synthesizer calibration	Yes	68
0x25	FSCAL1	Frequency synthesizer calibration	Yes	68
0x26	FSCAL0	Frequency synthesizer calibration	Yes	69
0x27	RCCTRL1	RC oscillator configuration	Yes	69
0x28	RCCTRL0	RC oscillator configuration	Yes	69
0x29	FSTEST	Frequency synthesizer calibration control	No	69
0x2A	PTEST	Production test	No	69
0x2B	AGCTEST	AGC test	No	69
0x2C	TEST2	Various test settings	No	70
0x2D	TEST1	Various test settings	No	70
0x2E	TEST0	Various test settings	No	70

 Table 35: Configuration Registers Overview





Address	Register	Description	Details on page number
0x30 (0xF0)	PARTNUM	Part number for <i>CC2500</i>	70
0x31 (0xF1)	VERSION	Current version number	70
0x32 (0xF2)	FREQEST	Frequency Offset Estimate	70
0x33 (0xF3)	LQI	Demodulator estimate for Link Quality	71
0x34 (0xF4)	RSSI	Received signal strength indication	71
0x35 (0xF5)	MARCSTATE	Control state machine state	71
0x36 (0xF6)	WORTIME1	High byte of WOR timer	72
0x37 (0xF7)	WORTIME0	Low byte of WOR timer	72
0x38 (0xF8)	PKTSTATUS	Current GDOx status and packet status	72
0x39 (0xF9)	VCO_VC_DAC	Current setting from PLL calibration module	72
0x3A (0xFA)	TXBYTES	Underflow and number of bytes in the TX FIFO	72
0x3B (0xFB)	RXBYTES	Overflow and number of bytes in the RX FIFO	72

Table 36: Status Registers Overview





Г	Write		R	ead	1
	Single byte Burst		Single byte	Burst	
0x00	+0x00	+0x40	+0x80	+0xC0	
0x00		IOCI			
0x02	IOCFG0				
0x03		FIFO	THR		
0x04		SYN			
0x05		SYN			
0x06	PKTLEN PKTCTRL1				
0x07 0x08		PKTC			
0x00		AD			
0x0A		CHA			
0x0B		FSC	rrl1		
0x0C		FSC	rrl0		
0x0D		FRE			
0x0E		FRE			-
0x0F		FRE			
0x10 0x11		MDM0 MDM0			ible
0x11		MDM			sso
0x13		MDM			d ss
0x14		MDM			R/W configuration registers, burst access possible
0x15		DEVI	ATN		st a
0x16		MCS	SM2		pur
0x17		MCS			ers,
0x18		MCS			gist
0x19 0x1A		FOC			u re
0x1A 0x1B		AGCC			ratic
0x1C		AGCC			ligu
0x1D		AGCC	TRL0		cou
0x1E	WOREVT1				
0x1F	WOREVT0				
0x20	WORCTRL				
0x21 0x22	FREND1 FREND0				
0x22 0x23	FRENDU FSCAL3				
0x24	FSCAL2				
0x25	FSCAL1				
0x26	FSCALO				
0x27		RCC			-
0x28		RCC			
0x29 0x2A		FST			
0x2B		AGC			
0x2C		TES			
0x2D		TES	ST1		
0x2E		TES	ST0		
0x2F				1	
0x30	SRES		SRES	PARTNUM	
0x31 0x32	SFSTXON SXOFF		SFSTXON SXOFF	VERSION FREQEST	(fund)
0x32 0x33	SCAL		SCAL	LQI	ad c
0x34	SRX		SRX	RSSI	s (re
0x35	STX		STX	MARCSTATE	sters
0x36	SIDLE		SIDLE	WORTIME1	regi
0x37	SAFC		SAFC	WORTIME0	tus
0x38	SWOR		SWOR	PKTSTATUS	Sta ters
0x39	SPWD		SPWD	VCO VC DAC TXBYTES	es, ∍gist
0x3A 0x3B	SFRX SFTX		SFRX SFTX	RXBYTES	strot te re
0x3C	SWORRST		SWORRST		d S S pr
0x3D	SNOP		SNOP		Command Strobes, Status registers (read only) and multi byte registers
0x3E	PATABLE	PATABLE	PATABLE	PATABLE	Com
0x3F	TX FIFO	TX FIFO	RX FIFO	RX FIFO	0.0

Table 37: SPI Address Space

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31.1 Configuration Register Details – Registers with preserved values in sleep state

Bit	Field Name	Reset	R/W	Description
7	Reserved		R0	
6	gdo2_INV	0	R/W	Invert output, i.e. select active low (1) / high (0)
5:0	GDO2_CFG[5:0]	41 (0x29)	R/W	Default is CHIP_RDY (see Table 33 on page 46). Should be set to 3-state for lowest power down current.

0x00: IOCFG2 - GDO2 output pin configuration

0x01: IOCFG1 – GDO1 output pin configuration

Bit	Field Name	Reset	R/W	Description
7	GDO_DS	0	R/W	Set high (1) or low (0) output drive strength on the GDO pins.
6	GDO1_INV	0	R/W	Invert output, i.e. select active low (1) / high (0)
5:0	GDO1_CFG[5:0]	46 (0x2E)	R/W	Default is 3-state (see Table 33 on page 46)

0x02: IOCFG0 – GDO0 output pin configuration

Bit	Field Name	Reset	R/W	Description
7	TEMP_SENSOR_ENABLE	0	R/W	Enable analog temperature sensor. Write 0 in all other register bits when using temperature sensor.
6	gdo0_ inv	0	R/W	Invert output, i.e. select active low (1) / high (0)
5:0	GDO0_CFG[5:0]	63 (0x3F)	R/W	Default is CLK_XOSC/192 (see Table 33 on page 46). Should be set to 3-state for lowest power down current.





Bit	Field Name	Reset	R/W	Description					
7:3	Reserved	0	R/W	Write 0 for compatibility with possible future extensions					
3:0	FIFO_THR[3:0]	7 (0111)	R/W	is exceeded v		and RX FIFO. The thre ytes in the FIFO is equ			
				Setting	Bytes in TX FIFO	Bytes in RX FIFO			
				0 (0000)	61	4			
				1 (0001)	57	8			
				2 (0010)	53	12			
				3 (0011)	49	16			
				4 (0100)	45	20			
				5 (0101)	41	24			
				6 (0110)	37	28			
				7 (0111)	33	32			
				8 (1000)	29	36			
				9 (1001)	25	40			
				10 (1010)	21	44			
				11 (1011)	17	48			
				12 (1100)	13	52			
				13 (1101)	9	56			
				14 (1110)	5	60			
				15 (1111)	1	64			

0x03: FIFOTHR – RX FIFO and TX FIFO thresholds

0x04: SYNC1 – Sync word, high byte

Bit	Field Name	Reset	R/W	Description
7:0	SYNC[15:8]	211 (0xD3)	R/W	8 MSB of 16-bit sync word

0x05: SYNC0 – Sync word, low byte

Bit	Field Name	Reset	R/W	Description
7:0	SYNC[7:0]	145 (0x91)	R/W	8 LSB of 16-bit sync word

0x06: PKTLEN – Packet length

Bit	Field Name	Reset	R/W	Description
7:0	PACKET_LENGTH	255 (0xFF)	R/W	Indicates the packet length when fixed length packets are enabled. If variable length packets are used, this value indicates the maximum length packets allowed.





Bit	Field Name	Reset	R/W	Descriptio	on
7:5	PQT[2:0]	0 (000)	R/W	Preamble quality estimator threshold. The preamble quality estimator increases an internal counter by one each time a bit is received that is different from the previous bit, and decreases th counter by 4 each time a bit is received that is the same as the last bit. The counter saturates at 0 and 31.	
					d of 4·PQT for this counter is used to gate sync word When PQT=0 a sync word is always accepted.
4	Reserved	0	R/W		
3	CRC_AUTOFLUSH	0	R/W	requires th	tomatic flush of RX FIFO when CRC in not OK. This nat only one packet is in the RXIFIFO and that packet mited to the RX FIFO size.
2	APPEND_STATUS	1	R/W	of the pacl	bled, two status bytes will be appended to the payload ket. The status bytes contain RSSI and LQI values, as e CRC OK flag.
1:0	ADR_CHK[1:0]	0 (00)	R/W	Controls a	ddress check configuration of received packages.
				Setting	Address check configuration
				0 (00)	No address check
				1 (01)	Address check, no broadcast
				2 (10)	Address check, 0 (0x00) broadcast
				3 (11)	Address check, 0 (0x00) and 255 (0xFF) broadcast

0x07: PKTCTRL1 – Packet automation control





Bit	Field Name	Reset	R/W	Descriptio	on
7	Reserved		R0		
6	WHITE_DATA	1	R/W	Turn data	whitening on / off
				0: Whiteni 1: Whiteni	
5:4	PKT_FORMAT[1:0]	0 (00)	R/W	Format of	RX and TX data
				Setting	Packet format
				0 (00)	Normal mode, use FIFOs for RX and TX
				1 (01)	Serial Synchronous mode, used for backwards compatibility. Data in on GDO0
				2 (10)	Random TX mode; sends random data using PN9 generator. Used for test. Works as normal mode, setting 0 (00), in RX.
				3 (11)	Asynchronous transparent mode. Data in on ${\tt GDO0}$ and Data out on either of the GDO pins
3	CC2400_EN	0	R/W	Enable CO CC2400.	C2400 support. Use same CRC implementation as
2	CRC_EN	1	R/W	1: CRC ca	lculation in TX and CRC check in RX enabled
				0: CRC dis	sabled for TX and RX
1:0	LENGTH_CONFIG[1:0]	1 (01)	R/W	Configure	the packet length
				Setting	Packet length configuration
				0 (00)	Fixed length packets, length configured in PKTLEN register
				1 (01)	Variable length packets, packet length configured by the first byte after sync word
				2 (10)	Enable infinite length packets
				3 (11)	Reserved

0x08: PKTCTRL0 – Packet automation control

0x09: ADDR – Device address

Bit	Field Name	Reset	R/W	Description
7:0	DEVICE_ADDR[7:0]	0 (0x00)	R/W	Address used for packet filtration. Optional broadcast addresses are 0 (0x00) and 255 (0xFF).

0x0A: CHANNR – Channel number

Bit	Field Name	Reset	R/W	Description
7:0	CHAN[7:0]	0 (0x00)	R/W	The 8-bit unsigned channel number, which is multiplied by the channel spacing setting and added to the base frequency.





Bit	Field Name	Reset	R/W	Description
7:5	Reserved		R0	
4:0	FREQ_IF[4:0]	10 (0x0F)	R/W	The desired IF frequency to employ in RX. Subtracted from FS base frequency in RX and controls the digital complex mixer in the demodulator. $f_{IF} = \frac{f_{XOSC}}{2^{10}} \cdot FREQ_IF$ The default value gives an IF frequency of 254 kHz, assuming a 26.0 MHz crystal.

0x0B: FSCTRL1 – Frequency synthesizer control

0x0C: FSCTRL0 – Frequency synthesizer control

Bit	Field Name	Reset	R/W	Description
7:0	FREQOFF[7:0]	0 (0x00)	R/W	Frequency offset added to the base frequency before being used by the FS. (2-complement). Resolution is $F_{XTAL}/2^{14}$ (1.59 - 1.65 kHz); range is ±202 kHz to ±210 kHz, dependent of XTAL frequency.

0x0D: FREQ2 – Frequency control word, high byte

Bit	Field Name	Reset	R/W	Description			
7:6	FREQ[23:22]	1 (01)	R	FREQ[23:22] i 95 with 26-27		the FREQ2 register is in the range 85 to	
5:0	FREQ[21:16]	30 (0x1E)	R/W	FREQ[23:0] is the base frequency for the frequency synthesiser in increments of $F_{XOSC}/2^{16}$. $f_{carrier} = \frac{f_{XOSC}}{2^{16}} \cdot FREQ[23:0]$ The default frequency word gives a base frequency of 2464 MHz, assuming a 26.0 MHz crystal. With the default channel spacing settings, the following FREQ2 values and channel numbers can be used:			
				FREQ2	Base frequency	Frequency range (CHAN numbers)	
				91 (0x5B)	2386 MHz	2400.2-2437 MHz (71-255)	
				92 (0x5C)	2412 MHz	2412-2463 MHz (0-255)	
				93 (0x5D)	2438 MHz	2431-2483.4 MHz (0-227)	
				94 (0x5E)	2464 MHz	2464-2483.4 MHz (0-97)	

0x0E: FREQ1 – Frequency control word, middle byte

Bit	Field Name	Reset	R/W	Description
7:0	FREQ[15:8]	196 (0xC4)	R/W	Ref. FREQ2 register

0x0F: FREQ0 – Frequency control word, low byte

Bit	Field Name	Reset	R/W	Description
7:0	FREQ[7:0]	236 (0xEC)	R/W	Ref. FREQ2 register







0x10: MDMCFG4 – Modem configuration

Bit	Field Name	Reset	R/W	Description
7:6	CHANBW_E[1:0]	2 (10)	R/W	
5:4	CHANBW_M[1:0]	0 (00)	R/W	Sets the decimation ratio for the delta-sigma ADC input stream and thus the channel bandwidth. $BW_{channel} = \frac{f_{XOSC}}{8 \cdot (4 + CHANBW_M) \cdot 2^{CHANBW_E}}$ The default values give 203 kHz channel filter bandwidth, assuming a 26.0 MHz crystal.
3:0	DRATE_E[3:0]	12 (1100)	R/W	The exponent of the user specified symbol rate

0x11: MDMCFG3 – Modem configuration

Bit	Field Name	Reset	R/W	Description
7:0	DRATE_M[7:0]	34 (0x22)	R/W	The mantissa of the user specified symbol rate. The symbol rate is configured using an unsigned, floating-point number with 9-bit mantissa and 4-bit exponent. The 9 th bit is a hidden '1'. The resulting data rate is: $R_{DATA} = \frac{(256 + DRATE _M) \cdot 2^{DRATE _E}}{2^{28}} \cdot f_{XOSC}$ The default values give a data rate of 115.051 kbps (closest setting to 115.2 kbps), assuming a 26.0 MHz crystal.





0x12: MDMCFG2 – Modem configuration

Bit	Field Name	Reset	R/W	Description
7	DEM_DCFILT_OFF	0	R/W	Disable digital DC blocking filter before demodulator.
				0 = Enable (better sensitivity for data rates ≤ 250 kbps)
				1 = Disable (reduced current)
				The recommended IF frequency changes when the DC blocking is disabled.
6:4	MOD_FORMAT[2:0]	0 (000)	R/W	The modulation format of the radio signal
				Setting Modulation format
				0 (000) 2-FSK
				1 (001) GFSK
				2 (010) -
				3 (011) OOK
				4 (100) -
				5 (101) -
				6 (110) -
				7 (111) MSK
3	MANCHESTER_EN	0	R/W	Enables Manchester encoding/decoding.
				0 = Disable
				1 = Enable
2:0	SYNC_MODE[2:0]	2 (010)	R/W	Combined sync-word qualifier mode.
				The values 0 (000) and 4 (100) disables sync word transmission in TX and sync word detection in RX.
				The values 1 (001), 2 (001), 5 (101) and 6 (110) enables 16-bit sync word transmission in TX and 16- bits sync word detection in RX. Only 15 of 16 bits need to match in RX when using setting 1 (001) or 5 (101). The values 3 (011) and 7 (111) enables repeated sync word transmission in RX and 32-bits sync word detection in RX (only 30 of 32 bits need to match).
				Setting Sync-word qualifier mode
				0 (000) No preamble/sync
				1 (001) 15/16 sync word bits detected
				2 (010) 16/16 sync word bits detected
				3 (011) 30/32 sync word bits detected
				4 (100) No preamble/sync, carrier-sense above threshold
				5 (101) 15/16 + carrier-sense above threshold
				6 (110) 16/16 + carrier-sense above threshold
				7 (111) 30/32 + carrier-sense above threshold





Bit	Field Name	Reset	R/W	Description
7	FEC_EN	0	R/W	Enable Forward Error Correction (FEC) with interleaving for packet payload
				0 = Disable
				1 = Enable
6:4	NUM_PREAMBLE[2:0]	2 (010)	R/W	Sets the minimum number of preamble bytes to be transmitted
				Setting Number of preamble bytes
				0 (000) 2
				1 (001) 3
				2 (010) 4
				3 (011) 6
				4 (100) 8
				5 (101) 12
				6 (110) 16
				7 (111) 24
3:2	Reserved		R0	
1:0	CHANSPC_E[1:0]	2 (10)	R/W	2 bit exponent of channel spacing

0x13: MDMCFG1 – Modem configuration

0x14: MDMCFG0 – Modem configuration

Bit	Field Name	Reset	R/W	Description
7:0	CHANSPC_M[7:0]	248 (0xF8)	R/W	8-bit mantissa of channel spacing (initial 1 assumed). The channel spacing is multiplied by the channel number CHAN and added to the base frequency. It is unsigned and has the format: $\Delta f_{CHANNEL} = \frac{f_{XOSC}}{2^{18}} \cdot (256 + CHANSPC_M) \cdot 2^{CHANSPC_E} \cdot CHAN$ The default values give 199.951 kHz channel spacing (the closest setting to 200 kHz), assuming 26.0 MHz crystal frequency.





0x15: DEVIATN – Modem deviation setting

Bit	Field Name	Reset	R/W	Description
7	Reserved		R0	
6:4	DEVIATION_E[2:0]	4 (100)	R/W	Deviation exponent
3	Reserved		R0	
2:0	DEVIATION_M[2:0]	7 (111)	R/W	When MSK modulation is enabled:
				Sets fraction of symbol period used for phase change.
				When FSK modulation is enabled:
				Deviation mantissa, interpreted as a 4-bit value with MSB implicit 1. The resulting FSK deviation is given by:
				$f_{dev} = \frac{f_{xosc}}{2^{17}} \cdot (8 + DEVIATION _M) \cdot 2^{DEVIATION_E}$
				The default values give ± 47.607 kHz deviation, assuming 26.0 MHz crystal frequency.

0x16: MCSM2 – Main Radio Control State Machine configuration
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Bit	Field Name	Reset	R/W	Description
7:5	Reserved		R0	Reserved
4	RX_TIME_RSSI	0	R/W	Direct RX termination based on RSSI measurement (carrier sense). For OOK modulation, RX times out if there is no carrier sense in the first 8 symbol periods.
3	RX_TIME_QUAL	0	R/W	When the RX_TIME timer expires the chip stays in RX mode if sync word is found when RX_TIME_QUAL=0, or either sync word is found or PQT is set when RX_TIME_QUAL=1.
2:0	RX_TIME[2:0]	7 (111)	R/W	Timeout for sync word search in RX. The timeout is relative to the programmed EVENT0 timeout, which means that the duty cycle can be set in wake-on-radio (WOR) mode. The RX timeout is scaled by 1 bit less than the EVENT0 timeout with respect to the WORCTRL.WOR_RES setting, as very long timeouts probably also will use very low RX duty cycles.
				Setting RX timeout Duty cycle, WOR
				0 (000) T _{EVENT0} / 2 ^(3+WOR_RES) 12.5% / 2 ^{WOR_RES}
				1 (001) T _{EVENT0} / 2 ^(4+WOR_RES) 6.25% / 2 ^{WOR_RES}
				2 (010) T _{EVENT0} / 2 ^(5+WOR_RES) 3.125% / 2 ^{WOR_RES}
				3 (011) T _{EVENT0} / 2 ^(6+WOR_RES) 1.563% / 2 ^{WOR_RES}
				4 (100) T _{EVENT0} / 2 ^(7+WOR_RES) 0.781% / 2 ^{WOR_RES}
				5 (101) T _{EVENT0} / 2 ^(8+WOR_RES) 0.391% / 2 ^{WOR_RES}
				6 (110) T _{EVENT0} / 2 ^(9+WOR_RES) 0.195% / 2 ^{WOR_RES}
				7 (111) Until end of packet N/A (no timeout)
				Note that the RC oscillator must be enabled in order to use setting 0-6, because the timeout counts RC oscillator periods. WOR mode does not need to be enabled. The timeout counter resolution is limited: With RX_TIME=0, the timeout count is given by the 13 MSBs of EVENT0, decreasing to the 7 MSBs of EVENT0 with RX_TIME=6.





Bit	Field Name	Reset	R/W	Description
7:6	Reserved		R0	
5:4	CCA_MODE[1:0]	3 (11)	R/W	Selects CCA_MODE; Reflected in CCA signal
				Setting Clear channel indication
				0 (00) Always
				1 (01) If RSSI below threshold
				2 (10) Unless currently receiving a packet
				3 (11) If RSSI below threshold unless currently receiving a packet
3:2	RXOFF_MODE[1:0]	0 (00)	R/W	Select what should happen when a packet has been received
				Setting Next state after finishing packet reception
				0 (00) IDLE
				1 (01) FSTXON
				2 (10) TX
				3 (11) Stay in RX
				It is not possible to set RXOFF_MODE to be TX or FSTXON and at the same time use CCA.
1:0	TXOFF_MODE[1:0]	0 (00)	R/W	Select what should happen when a packet has been sent (TX)
				Setting Next state after finishing packet transmission
				0 (00) IDLE
				1 (01) FSTXON
				2 (10) Stay in TX (start sending preamble)
				3 (11) RX

0x17: MCSM1 – Main Radio Control State Machine configuration





Bit	Field Name	Reset	R/W	Description
7:6	Reserved		R0	
5:4	FS_AUTOCAL[1:0]	0 (00)	R/W	Automatically calibrate when going to RX or TX, or back to IDLE
				Setting When to perform automatic calibration
				0 (00) Never (manually calibrate using SCAL strobe)
				1 (01) When going from IDLE to RX or TX (or FSTXON)
				2 (10) When going from RX or TX back to IDLE
				3 (11) Every 4 th time when going from RX or TX to IDLE
				In some automatic wake-on-radio (WOR) applications, using setting 3 (11) can significantly reduce current consumption.
3:2	PO_TIMEOUT	1 (01)	R/W	Programs the number of times the six-bit ripple counter must expire before CHP_RDY_N goes low. Values other than 0 (00) are most useful when the XOSC is left on during power-down.
				Setting Expire count Timeout after XOSC start
				0 (00) 1 Approx. 2.3 – 2.7 μs
				1 (01) 16 Approx. 37 – 43 μs
				2 (10) 64 Approx. 146 – 171 µs
				3 (11) 256 Approx. 585 – 683 µs
				Exact timeout depends on crystal frequency.
1	PIN_CTRL_EN	0	R/W	Enables the pin radio control option
0	XOSC_FORCE_ON	0	R/W	Force the XOSC to stay on in the SLEEP state.

0x18: MCSM0 – Main Radio Control State Machine configuration

0x19: FOCCFG – Frequency Offset Compensation configuration

Bit	Field Name	Reset	R/W	Description
7:6	Reserved		R0	
5:0	FOCCFG[5:0]	54 (0x36)	R/W	Frequency offset compensation configuration. The value to use in this register is given by the SmartRF [®] Studio software.

0x1A: BSCFG – Bit Synchronization configuration

Bit	Field Name	Reset	R/W	Description
7:0	BSCFG[7:0]	108 (0x6C)	R/W	Bit Synchronization configuration. The value to use in this register is given by the SmartRF $^{\mbox{\ensuremath{\$}}}$ Studio software.





Bit	Field Name	Reset	R/W	Description	1
7:6	MAX_DVGA_GAIN[1:0]	0 (00)	R/W	Reduces the	e maximum allowable DVGA gain.
				Setting	Allowable DVGA settings
				0 (00)	All gain settings can be used
				1 (01)	The highest gain setting can not be used
				2 (10)	The 2 highest gain settings can not be used
				3 (11)	The 3 highest gain settings can not be used
5:3	MAX_LNA_GAIN[2:0]	0 (000)	R/W	Sets the ma maximum pe	ximum allowable LNA + LNA 2 gain relative to the ossible gain.
				Setting	Maximum allowable LNA + LNA 2 gain
				0 (000)	Maximum possible LNA + LNA 2 gain
				1 (001)	Approx. 2.6 dB below maximum possible gain
				2 (010)	Approx. 6.1 dB below maximum possible gain
				3 (011)	Approx. 7.4 dB below maximum possible gain
				4 (100)	Approx. 9.2 dB below maximum possible gain
				5 (101)	Approx. 11.5 dB below maximum possible gain
				6 (110)	Approx. 14.6 dB below maximum possible gain
				7 (111)	Approx. 17.1 dB below maximum possible gain
2:0	MAGN_TARGET[2:0]	3 (011)	R/W		set the target value for the averaged amplitude from hannel filter (1 LSB = 0 dB).
				Setting	Target amplitude from channel filter
				0 (000)	24 dB
				1 (001)	27 dB
				2 (010)	30 dB
				3 (011)	33 dB
				4 (100)	36 dB
				5 (101)	38 dB
				6 (110)	40 dB
				7 (111)	42 dB

0x1B: AGCCTRL2 - AGC control





0x1C: AGCCTRL1 - AGC control

Bit	Field Name	Reset	R/W	Description
7	Reserved		R0	
6	AGC_LNA_PRIORITY	1	R/W	Selects between two different strategies for LNA and LNA 2 gain adjustment. When 1, the LNA gain is decreased first. When 0, the LNA 2 gain is decreased to minimum before decreasing LNA gain.
5:4	CARRIER_SENSE_REL_THR[1:0]	0 (00)	R/W	Sets the relative change threshold for asserting carrier sense
				Setting Carrier sense relative threshold
				0 (00) Relative carrier sense threshold disabled
				1 (01) 6 dB increase in RSSI value
				2 (10) 10 dB increase in RSSI value
				3 (11) 14 dB increase in RSSI value
3:0	CARRIER_SENSE_ABS_THR[3:0]	0 (0000)	R/W	Sets the absolute RSSI threshold for asserting carrier sense. The 2-complement signed threshold is programmed in steps of 1 dB and is relative to the MAGN_TARGET setting.
				Setting Carrier sense absolute threshold
				(Equal to channel filter amplitude when AGC has not decreased gain)
				-8 (1000) Absolute carrier sense threshold disabled
				-7 (1001) 7 dB below MAGN_TARGET setting
				-1 (1111) 1 dB below MAGN_TARGET setting
				0 (0000) At MAGN_TARGET setting
				1 (0001) 1 dB above MAGN_TARGET setting
				7 (0111) 7 dB above MAGN_TARGET setting

0x1D: AGCCTRL0 – AGC control

Bit	Field Name	Reset	R/W	Description
7:0	AGCCTRL0[7:0]	145 (0x91)	R/W	AGC control register. The value to use in this register is given by the SmartRF $^{\ensuremath{\mathbb{S}}}$ Studio software.

0x1E: WOREVT1 – High byte Event0 timeout

Bit	Field Name	Reset	R/W	Description
7:0	EVENT0[15:8]	135 (0x87)	R/W	High byte of Event 0 timeout register $t_{Event0} = \frac{750}{f_{XOSC}} \cdot EVENT0 \cdot 2^{5 \cdot WOR_RES}$





Bit	Field Name	Reset	R/W	Description
7:0	EVENT0[7:0]	107 (0x6B)	R/W	Low byte of Event 0 timeout register. The default Event 0 value gives 1.0s timeout, assuming a 26.0 MHz crystal
				26.0 MHz crystal.

Bit **Field Name** Reset R/W Description RC_PD R/W Power down signal to RC oscillator. When written to 0, automatic 7 1 initial calibration will be performed 6:4 EVENT1[2:0] 7 (111) R/W Timeout setting from register block. Decoded to Event 1 timeout. RC oscillator clock frequency equals $F_{XOSC}/750$, which is 34.7-36 kHz, depending on crystal frequency. The table below lists the number of clock periods after Event 0 before Event 1 times out. Setting WOR AUTOSYNC=0 WOR AUTOSYNC=1 0 (000) 4 (0.111 – 0.115 ms) 16(0.44 - 0.46 ms)1 (001) 6 (0.167 - 0.173 ms) 24 (0.67 - 0.69 ms) 2 (010) 8 (0.222 - 0.230 ms) 32 (0.89 - 0.92 ms) 3 (011) 12 (0.333 - 0.346 ms) 48 (1.33 - 1.38 ms) 4 (100) 16 (0.444 - 0.462 ms) 64 (1.78 - 1.85 ms) 24 (0.667 – 0.692 ms) 5 (101) 96 (2.67 - 2.77 ms) 6 (110) 32 (0.889 - 0.923 ms) 128 (3.56 - 3.69 ms) 7 (111) 48 (1.333 - 1.385 ms) 192 (5.33 - 5.54 ms) 3 RC_CAL 1 R/W Enables (1) or disables (0) the RC oscillator calibration. Included for debug/test purposes only. 2 Reserved R0 Controls the Event 0 resolution and maximum timeout of the WOR WOR_RES 1:0 0 (00) R/W module: Resolution (1 LSB) Max timeout Settina 1.8 - 1.9 seconds 0 (00) 1 period (28 - 29 µs) 2^5 periods (0.89 - 0.92 ms) 1 (01) 58-61 seconds 2^{10} periods (28 – 30 ms) 2 (10) 31 - 32 minutes 2^{15} periods (0.91 - 0.94 s) 16.5 - 17.2 hours 3 (11) Adjusting the resolution does not affect the resolution of the WOR time readout registers WORTIME1/WORTIME0.

0x20: WORCTRL – Wake On Radio control

0x21: FREND1 – Front end RX configuration

Bit	Field Name	Reset	R/W	Description
7:0	FREND1[7:0]	166 (0xA6)	R/W	Front end RX configuration. The value to use in this register is given by the SmartRF [®] Studio software.







0x22: FREND0 – Front end TX configuration

Bit	Field Name	Reset	R/W	Description
7:6	Reserved		R0	
5:4	LODIV_BUF_CURRENT_TX[1:0]	1 (01)	R/W	Adjusts current TX LO buffer (input to PA). The value to use in this field is given by the SmartRF [®] Studio software.
3	Reserved		R0	
2:0	PA_POWER[2:0]	0 (000)	R/W	Selects PA power setting. This value is an index to the PATABLE, which can be programmed with up to 8 different PA settings. The PATABLE settings from index '0' to the PA_POWER value are used for power ramp-up/ramp-down at the start/end of transmission in all TX modulation formats.

0x23: FSCAL3 – Frequency synthesizer calibration

Bit	Field Name	Reset	R/W	Description
7:6	FSCAL3[7:6]	2 (10)	R/W	Frequency synthesizer calibration configuration. The value to write in this register before calibration is given by the SmartRF [®] Studio software.
5:4	CHP_CURR_CAL_EN[1:0]	2 (10)	R/W	Disable charge pump calibration stage when 0
3:0	FSCAL3[3:0]	9 (1001)	R/W	Frequency synthesizer calibration result register. Fast frequency hopping without calibration for each hop can be done by calibrating upfront for each frequency and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values. Between each frequency hop, calibration can be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency.

0x24: FSCAL2 – Frequency synthesizer calibration

Bit	Field Name	Reset	R/W	Description
7:6	Reserved		R0	
5:0	FSCAL2[5:0]	10 (0x0A)	R/W	Frequency synthesizer calibration result register. Fast frequency hopping without calibration for each hop can be done by calibrating upfront for each frequency and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values. Between each frequency hop, calibration can be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency.

Bit	Field Name	Reset	R/W	Description
7:6	Reserved		R0	
5:0	FSCAL1[5:0]	32 (0x20)	R/W	Frequency synthesizer calibration result register. Fast frequency hopping without calibration for each hop can be done by calibrating upfront for each frequency and saving the resulting FSCAL3, FSCAL2 and FSCAL1 register values. Between each frequency hop, calibration can be replaced by writing the FSCAL3, FSCAL2 and FSCAL1 register values corresponding to the next RF frequency.





Bit	Field Name	Reset	R/W	Description
7	Reserved		R0	
4:0	FSCAL0[6:0]	13 (0x0D)	R/W	Frequency synthesizer calibration control. The value to use in this register is given by the SmartRF $^{\rm \$}$ Studio software.

0x26: FSCAL0 – Frequency synthesizer calibration

0x27: RCCTRL1 – RC oscillator configuration

Bit	Field Name	Reset	R/W	Description
7	Reserved	0	R0	
6:0	RCCTRL1[6:0]	65 (0x41)	R/W	RC oscillator configuration. Do not write to this register.

0x28: RCCTRL0 – RC oscillator configuration

Bit	Field Name	Reset	R/W	Description
7	Reserved	0	R0	
6:0	RCCTRL0[6:0]	0 (0x00)	R/W	RC oscillator configuration. Do not write to this register.

31.2 Configuration Register Details – Registers that lose programming in sleep state

0x29: FSTEST – Frequency synthesizer calibration control

Bit	Field Name	Reset	R/W	Description
7:0	FSTEST[7:0]	87 (0x59)	R/W	For test only. Do not write to this register.

0x2A: PTEST – Production test

Bit	Field Name	Reset	R/W	Description
7	PTEST[7:0]	127 (0x7F)	R/W	Writing 0xBF to this register makes the on-chip temperature sensor available in the IDLE state. The default 0x7F value should then be written back before leaving the IDLE state. Other use of this register is for test only.

0x2B: AGCTEST - AGC test

Bit	Field Name	Reset	R/W	Description
7:0	AGCTEST[7:0]	63 (0x3F)	R/W	For test only. Do not write to this register.





0x2C: TEST2 – Various test settings

Bit	Field Name	Reset	R/W	Description
7:0	TEST2[7:0]	152 (0x88)	R/W	The value to use in this register is given by the SmartRF [®] Studio software.

0x2D: TEST1 – Various test settings

Bit	Field Name	Reset	R/W	Description
7:0	TEST1[7:0]	49 (0x31)	R/W	The value to use in this register is given by the $\textsc{Smart}\textsc{RF}^{\circledast}$ Studio software.

0x2E: TEST0 – Various test settings

Bit	Field Name	Reset	R/W	Description
7:0	TEST0[7:0]	11 (0x0B)	R/W	The value to use in this register is given by the $\mbox{SmartRF}^{\circledast}$ Studio software.

31.3 Status register details

0x30 (0xF0): PARTNUM – Chip ID

Bit	Field Name	Reset	R/W	Description
7:0	PARTNUM[7:0]	128 (0x80)	R	Chip part number

0x31 (0xF1): VERSION – Chip ID

Bit	Field Name	Reset	R/W	Description
7:0	VERSION[7:0]	3 (0x03)	R	Chip version number.

0x32 (0xF2): FREQEST - Frequency Offset Estimate from demodulator

Bit	Field Name	Reset	R/W	Description
7:0	FREQOFF_EST		R	The estimated frequency offset (two's complement) of the carrier. Resolution is $F_{XTAL}/2^{14}$ (1.59 - 1.65 kHz); range is ±202 kHz to ±210 kHz, dependent of XTAL frequency. Frequency offset compensation is only supported for FSK and MSK modulation. This register will read 0 when using OOK modulation.





0x33 (0xF3): LQI – Demodulator estimate for Link Quality

Bit	Field Name	Reset	R/W	Description
7	Reserved			
6:0	LQI_EST[6:0]		R	The Link Quality Indicator estimates how easily a received signal can be demodulated. Calculated over the 64 symbols following the sync word (first 8 packet bytes for 2-ary modulation).

0x34 (0xF4): RSSI – Received signal strength indication

Bit	Field Name	Reset	R/W	Description
7:0	RSSI		R	Received signal strength indicator

0x35 (0xF5): MARCSTATE – Main Radio Control State Machine state

Bit	Field Name	Reset	R/W	Description		
7:5	Reserved		R0			
4:0	MARC_STATE[4:0]		R	Main Radio C	Control FSM State	
				Value	State name	State (Figure 11, page 34)
				0 (0x00)	SLEEP	SLEEP
				1 (0x01)	IDLE	IDLE
				2 (0x02)	XOFF	XOFF
				3 (0x03)	VCOON_MC	MANCAL
				4 (0x04)	REGON_MC	MANCAL
				5 (0x05)	MANCAL	MANCAL
				6 (0x06)	VCOON	FS_WAKEUP
				7 (0x07)	REGON	FS_WAKEUP
				8 (0x08)	STARTCAL	CALIBRATE
				9 (0x09)	BWBOOST	SETTLING
				10 (0x0A)	FS_LOCK	SETTLING
				11 (0x0B)	IFADCON	SETTLING
				12 (0x0C)	ENDCAL	CALIBRATE
				13 (0x0D)	RX	RX
				14 (0x0E)	RX_END	RX
				15 (0x0F)	RX_RST	RX
				16 (0x10)	TXRX_SWITCH	TXRX_SETTLING
				17 (0x11)	RX_OVERFLOW	RX_OVERFLOW
				18 (0x12)	FSTXON	FSTXON
				19 (0x13)	ТХ	ТХ
				20 (0x14)	TX_END	ТХ
				21 (0x15)	RXTX_SWITCH	RXTX_SETTLING
				22 (0x16)	TX_UNDERFLOW	TX_UNDERFLOW
				numbers bec		the SLEEP or XOFF state will make the chip enter the FF states.







0x36 (0xF6): WORTIME1 – High byte of WOR time

Bit	Field Name	Reset	R/W	Description
7:0	TIME[15:8]		R	High byte of timer value in WOR module

0x37 (0xF7): WORTIME0 - Low byte of WOR time

Bit	Field Name	Reset	R/W	Description
7:0	TIME[7:0]		R	Low byte of timer value in WOR module

0x38 (0xF8): PKTSTATUS - Current GDOx status and packet status

Bit	Field Name	Reset	R/W	Description
7	Reserved			
6	CS		R	Carrier sense
5	PQT_REACHED		R	Preamble Quality reached
4	CCA		R	Clear channel assessment
3	SFD		R	Sync word found
2	GDO2		R	Current GDO2 value. Note: the reading gives the non-inverted value irrespective what IOCFG2.GDO2_INV is programmed to.
1	Reserved			
0	GDO0		R	Current GDO0 value. Note: the reading gives the non-inverted value irrespective what IOCFG0.GDO0_INV is programmed to.

0x39 (0xF9): VCO_VC_DAC - Current setting from PLL calibration module

Bit	Field Name	Reset	R/W	Description
7:0	VCO_VC_DAC[7:0]		R	Status register for test only.

0x3A (0xFA): TXBYTES – Underflow and number of bytes

Bit	Field Name	Reset	R/W	Description
7	TXFIFO_UNDERFLOW		R	
6:0	NUM_TXBYTES		R	Number of bytes in TX FIFO

0x3B (0xFB): RXBYTES - Overflow and number of bytes

Bit	Field Name	Reset	R/W	Description
7	RXFIFO_OVERFLOW		R	
6:0	NUM_RXBYTES		R	Number of bytes in RX FIFO





32 Package Description (QLP 20)

All dimensions are in millimetres, angles in degrees. NOTE: The *CC2500* is available in RoHS lead-free package only.



Figure 24: Package dimensions drawing

Package type		Α	A1	A2	D	D1	D2	Е	E1	E2	L	т	b	е
	Min	0.75	0.005	0.55	3.90	3.65		3.90	3.65		0.45	0.190	0.18	
QLP 20 (4x4)	Тур.	0.85	0.025	0.65	4.00	3.75	2.40	4.00	3.75	2.40	0.55		0.23	0.50
	Max	0.95	0.045	0.75	4.10	3.85		4.10	3.85		0.65	0.245	0.30	

Table 38: Package dimensions



32.1 Recommended PCB layout for package (QLP 20)



Figure 25: Recommended PCB layout for QLP 20 package

Note: The figure is an illustration only and not to scale. There are five 14 mil diameter via holes distributed symmetrically in the ground pad under the package. See also the *CC2500* EM reference design.

32.2 Package thermal properties

Thermal resistance					
Air velocity [m/s]	0				
Rth,j-a [K/W]	40.4				

Table 39: Thermal properties of QLP 20 package

32.3 Soldering information

The recommendations for lead-free reflow in IPC/JEDEC J-STD-020C should be followed.

32.4 Tray specification

CC2500 can be delivered in standard QLP 4x4mm shipping trays.

Tray Specification							
Package	Tray Width	Tray Height	Tray Length	Units per Tray			
QLP 20	135.9 mm	7.62 mm	322.6 mm	490			

Table 40: Tray specification







32.5 Carrier tape and reel specification

Tape and Reel Specification								
Package	Tape Width	Component Pitch	Hole Pitch	Reel Diameter	Units per Reel			
QLP 20	12 mm	8 mm	4 mm	13 inches	2500			

Carrier tape and reel is in accordance with EIA Specification 481.

Table 41: Carrier tape and reel specification

33 Ordering Information

Ordering part number	Description	Minimum Order Quantity (MOQ)
1167	CC2500 - RTY1 QLP20 RoHS Pb-free 490/tray	490 (tray)
1190	CC2500 - RTR1 QLP20 RoHS Pb-free 2500/T&R	2500 (tape and reel)
1192	CC2500 SK Sample kit 5pcs.	1
10069	CC2500_CC2550 DK Development Kit	1

Table 42: Ordering information

34 General Information

34.1 Document History

Revision	Date	Description/Changes
1.1	2005-10-20	MDMCFG2[7] used. 26-27 MHz crystal range. Chapter 15: description of the 2 optional append bytes. Added matching information. Added information about using a reference signal instead of a crystal. CRC can only be checked by append bytes or CRC_AUTOFLUSH. Added equation for calculating RSSI in dBm. Selectivity performance graphs added.
1.0	2005-01-24	First preliminary release.

Table 43: Document history

34.2 Product Status Definitions

Data Sheet Identification	Product Status	Definition		
Advance Information	Planned or Under Development	This data sheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary Engineering Samples and First Production		This data sheet contains preliminary data, and supplementary data will be published at a later date. Chipcon reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.		
No Identification Noted	Full Production	This data sheet contains the final specifications. Chipcon reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.		
Obsolete	Not In Production	This data sheet contains specifications on a product that has been discontinued by Chipcon. The data sheet is printed for reference information only.		

Table 44: Product status definitions





HH25111

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CC2500

35 Address Information

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